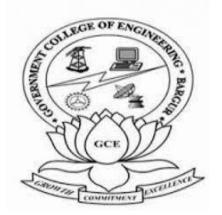
GOVERNMENT COLLEGE OF ENGINEERING, BARGUR

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

(ACCREDITED BY NBA)

P.G. FULLTIME M.E. - APPLIED ELECTRONICS CURRICULUM & SYLLABI (REGULATIONS – 2017)



GOVERNMENT COLLEGE OF ENGINEERING, BARGUR

Krishnagiri - 635104, Tamil Nadu Phone No: 04343 266 067 Website: <u>www.gcebargur.ac.in</u>

GOVERNMENT COLLEGE OF ENGINEERING, BARGUR DEPARTMENT OF ECE

VISION OF THE INSTITUTE

To provide world class engineers who are ethical and good citizens of our motherland

MISSION OF THE INSTITUTE

To groom the student community through learner centric quality lectures, laboratories, Library and value added training.

GOVERNMENT COLLEGE OF ENGINEERING, BARGUR DEPARTMENT OF ECE

VISION OF THE DEPARTMENT

We envision our students to be excellent engineers not only in the field of science and technology, but also embed the greatest values of human life. Our commitment lies in producing good citizens, comprehensive knowledge seekers and remains as an asset in building a strong and developed nation.

MISSION OF THE DEPARTMENT

- To achieve the vision we should have hard working faculty who use effective teaching methodologies.
- To impart knowledge in the latest trends of technical education.
- To prepare our young students to become professionally and morally sound engineers.
- To teach global standards in production and value based living through a truthful and technical approach.

PROGRAM EDUCATIONAL OBJECTIVES (PEO)

PEO1. To demonstrate the education skills that will enable to integrate fundamentals with advanced knowledge to provide solutions to complex electronics engineering problems.

PEO2. To provide a successful career in electronic system design or associated industries or research and higher education, or as entrepreneurs.

PEO3. To develop the ability and attitude to adapt to evolving technological challenges

PROGRAMME OUTCOMES (PO)

a) Graduates will demonstrate knowledge of fuzzy logic and matrix theory, random variables and probability functions, dynamic programming and queuing models.

b) Graduates will demonstrate an ability to identify, analyze and develop solutions to solve complex problems using digital signal processing techniques.

c) Graduates will demonstrate an ability to design advanced digital circuits and analyze them through Simulation and practice.

d) Graduates will demonstrate an ability to design digital and analog VLSI circuits and analyze them through simulation and practice and to understand and program advanced microprocessors and microcontrollers and analyze them for embedded applications.

e) Graduates will demonstrate an ability to visualize and work on laboratory and multi-disciplinary tasks.

f) Graduates will demonstrate skills to use modern electronics design and simulation tools (both software and hardware) to analyze problems.

g) Graduates will demonstrate knowledge of professional and ethical responsibilities.

h) Graduates will be able to communicate effectively in both verbal and written form.

i) Graduates will show the understanding of impact of engineering solutions on the society and also will be aware of contemporary issues.

j) Graduates will develop confidence for self-education and ability for lifelong learning.

k) Graduates will be able to participate and succeed in competitive examinations.

1) Graduates will demonstrate an ability as an individual or as a member of a team to solve complex and socially relevant engineering problems.

GOVERNMENT COLLEGE OF ENGINEERING BARGUR

Regulation – 2017

AUTONOMOUS

Curriculum for Full Time M.E.–Applied Electronics (Department of ECE)

From the Academic Year 2017 -2018 onwards

SEMESTER-I

| SL.No. | COURSE CODE | COURSE TITLE | CATEGORY | L | Т | Р | С | | | |
|--------|----------------|--|----------|----|---|---|----|--|--|--|
| THEOR | RY | | | | | | | | | |
| 1. | 17AEFC01 | Applied Mathematics for Electronics Engineers | FC | 4 | 0 | 0 | 4 | | | |
| 2. | 17AEPC02 | Advanced Digital System Design | PC | 3 | 0 | 0 | 3 | | | |
| 3. | 17AEPC03 | Advanced Digital Signal Processing | PC | 3 | 2 | 0 | 4 | | | |
| 4. | 17AEPC04 | Embedded System Design | PC | 3 | 0 | 0 | 3 | | | |
| 5. | 17AEPC05 | Modern communication techniques | PC | 3 | 0 | 0 | 3 | | | |
| 6. | | Professional Elective I | PC | 3 | 0 | 0 | 3 | | | |
| PRACT | PRACTICALS | | | | | | | | | |
| 7. | 17AEPC06 | Embedded System Design Laboratory | PC | 0 | 0 | 4 | 2 | | | |
| | | | TOTAL | 12 | 2 | 4 | 22 | | | |

SEMESTER-II

| SL.No. | COURSE CODE | COURSE TITLE | CATEGORY | L | Т | Р | С |
|--------|----------------|--|----------|----|---|---|----|
| THEOR | RY | | | | | | |
| 1. | 17AEPC07 | Soft Computing and Optimization Techniques | PC | 3 | 0 | 0 | 3 |
| 2. | 17AEPC08 | VLSI System Design | PC | 3 | 0 | 0 | 3 |
| 3. | 17AEPC09 | Hardware – Software Co-design | PC | 3 | 0 | 0 | 3 |
| 4. | 17AEPC10 | Internet of Things | PC | 3 | 0 | 0 | 3 |
| 5. | | Professional Elective II | PE | 3 | 0 | 0 | 3 |
| 6. | | Professional Elective III | PE | 3 | 0 | 0 | 3 |
| PRACT | TICALS | | | | | | |
| 7. | 17AEPC11 | VLSI System Design Laboratory | PC | 0 | 0 | 4 | 2 |
| 8. | 17AEEE12 | Term Paper Writing and Seminar | EEC | 0 | 0 | 2 | 1 |
| | • | · | TOTAL | 18 | 0 | 6 | 21 |

SEMESTER-III

| SL.No. | COURSE CODE | COURSE TITLE | CATEGORY | L | Т | Р | С |
|--------|----------------|---|----------|----|---|----|----|
| THEOI | RY | | | | | | |
| 1. | 17AEPC13 | Electronic Product design and development | PC | 3 | 0 | 0 | 3 |
| 2. | | Professional Elective IV | PE | 3 | 0 | 0 | 3 |
| 3. | | Professional Elective V | PE | 3 | 0 | 0 | 3 |
| PRACT | TICALS | | | | | | |
| 4. | 17AEEE14 | Project Work Phase I | EEC | 0 | 0 | 12 | 6 |
| | | | | | | | |
| | | | TOTAL | 12 | 0 | 12 | 15 |

SEMESTER-IV

| SL.No. | COURSE CODE | COURSE TITLE | CATEGORY | L | Т | Р | С |
|--------|----------------|-----------------------|----------|---|---|----|----|
| PRACT | TICALS | | | | | | |
| 1. | 17AEEE15 | Project Work Phase II | EEC | 0 | 0 | 24 | 12 |
| | | | TOTAL | 0 | 0 | 24 | 12 |

TOTAL NO. OF CREDITS: 70

| SL.NO | COURSE CODE | COURSETITLE | L | Т | Р | С |
|-------|-------------|-----------------------------------|---|---|----|----|
| 1. | 17AEEE12 | Term Paper Writing and Seminar | 0 | 0 | 2 | 1 |
| 2. | 17AEEE14 | Project Work Phase I | 0 | 0 | 12 | 6 |
| 3. | 17AEEE15 | Project Work Phase II | 0 | 0 | 24 | 12 |

PROFESSIONAL ELECTIVES (PE)

SEMESTER I

ELECTIVE I

| SL.NO | COURSE CODE | COURSETITLE | CATEGORY | L | Т | Р | С |
|-------|----------------|--|----------|---|---|---|---|
| 1. | 17AEPE01 | Digital Control Engineering | PE | 3 | 0 | 0 | 3 |
| 2. | 17AEPE02 | Computer Architecture | PE | 3 | 0 | 0 | 3 |
| 3. | 17AEPE03 | Digital VLSI design | PE | 3 | 0 | 0 | 3 |
| 4. | 17AEPE04 | Electromagnetic Interference and Compatibility | PE | 3 | 0 | 0 | 3 |

PROFESSIONAL ELECTIVES (PE)

SEMESTER II

ELECTIVE II

| SL.NO | COURSE CODE | COURSETITLE | CATEGORY | L | T | Р | С |
|-------|----------------|------------------------------------|----------|---|---|---|---|
| 1. | 17AEPE05 | CAD for VLSI | PE | 3 | 0 | 0 | 3 |
| 2. | 17AEPE06 | Nano Electronics | PE | 3 | 0 | 0 | 3 |
| 3. | 17AEPE07 | Sensors and measurement systems | PE | 3 | 0 | 0 | 3 |
| 4. | 17AEPE08 | MEMS and NEMS | PE | 3 | 0 | 0 | 3 |

SEMESTER II

ELECTIVE III

| SL.NO | COURSE CODE | COURSETITLE | CATEGORY | L | Т | Р | С |
|-------|----------------|---|----------|---|---|---|---|
| 1. | 17AEPE09 | DSP processor Architectures and Programming | PE | 3 | 0 | 0 | 3 |
| 2. | 17AEPE10 | RF System Design | PE | 3 | 0 | 0 | 3 |
| 3. | 17AEPE11 | Speech Signal Processing | PE | 3 | 0 | 0 | 3 |
| 4. | 17AEPE12 | Solid State Device Modeling and simulation | PE | 3 | 0 | 0 | 3 |

SEMESTER III

ELECTIVE IV

| SL.NO | COURSE CODE | COURSETITLE | CATEGORY | L | Т | Р | С |
|-------|----------------|---|----------|---|---|---|---|
| 1. | 17AEPE13 | Advanced Microprocessor and Microcontroller Architecture | PE | 3 | 0 | 0 | 3 |
| 2. | 17AEPE14 | System on Chip Design | PE | 3 | 0 | 0 | 3 |
| 3. | 17AEPE15 | Robotics | PE | 3 | 0 | 0 | 3 |
| 4. | 17AEPE16 | Physical Design of VLSI Circuits | PE | 3 | 0 | 0 | 3 |
| 5. | 17AEPE17 | High Performance Networks | PE | 3 | 0 | 0 | 3 |

SEMESTER III

ELECTIVE V

| SL.NO | COURSE CODE | COURSETITLE | CATEGORY | L | Т | Р | С |
|-------|----------------|---|----------|---|---|---|---|
| 1. | 17AEPE18 | Pattern Recognition | PE | 3 | 0 | 0 | 3 |
| 2. | 17AEPE19 | Secure Computing Systems | PE | 3 | 0 | 0 | 3 |
| 3. | 17AEPE20 | Signal Integrity for High Speed Design | PE | 3 | 0 | 0 | 3 |
| 4. | 17AEPE21 | Wireless AD-HOC and Sensor Networks | PE | 3 | 0 | 0 | 3 |

SEMESTER-I

| 17AEF(| C 01 | APPLIED MATHEMATICS FOR ELECTRONICS ENGINEERS | L | T | Р | C | | |
|------------|---------------------|---|--------|-------|--------|-----------|--|--|
| | | | 4 | 0 | 0 | 4 | | |
| OBJEC | TIVES | : | | | | L | | |
| • | To imp | part knowledge on fuzzy logic. | | | | | | |
| • | To und | lerstand the basic concepts of matrix theory and their applicat | ions. | | | | | |
| • | To find | the optimum solution of the random variables. | | | | | | |
| • | To und | lerstand the concepts of dynamic programming and queuing r | node | ls. | | | | |
| UNIT I | | FUZZY LOGIC | | | | | | |
| | logic – N | Multivalued logics – Fuzzy propositions – Fuzzy quantifiers. | | | | | | |
| UNIT I | [| MATRIX THEORY | | | | 9 | | |
| • | - | osition - Generalized Eigenvectors - Canonical basis - QR Singular value decomposition. | fact | oriza | ation | – Least | | |
| UNIT I | II | PROBABILITY AND RANDOM VARIABLE | | | | 9 | | |
| -Probabili | ity funct Geomet | oms of probability – Conditional probability – Baye's theore ion – Moments – Moment generating functions and their p ric, Uniform, Exponential, Gamma and Normal distributi | rope | rties | – B | inomial, | | |
| UNIT I | V | DYNAMIC PROGRAMMING | | | | 9 | | |
| • | | nming – Principle of optimality – Forward and backward recomming – Problem of dimensionality. | ursic | on – | App | lications | | |
| UNIT V | 7 | QUEUEING MODELS | | | | 9 | | |
| | | Markovian queues – Single and multi server models – Little l – Steady state analysis – Self service queue. | e's fo | rmu | la – I | Machine | | |
| | | TOTAL:60 PERI | OD | S | | | | |
| OUTCO | DMES : | | | | | | | |
| • | | epts of fuzzy sets, knowledge representation using fuzzy rul sitions and fuzzy quantifiers and applications of fuzzy logic. | es, f | uzzy | logi | c, fuzzy | | |

| • | Apply various methods in matrix theory to solve system of linear equations. |
|--------|--|
| • | Computation of probability and moments, standard distributions of discrete and continuous random variables and functions of a random variable. |
| • | Conceptualize the principle of optimality and sub-optimization, formulation and computational procedure of dynamic programming |
| • | Exposing the basic characteristic features of a queuing system and acquire skills in analyzing queuing models |
| • | Using discrete time Markov chains to model computer systems. |
| REFERE | INCES: |
| 1. | Bronson, R., "Matrix Operations", Schaum's Outline Series, McGraw Hill, 2011. |
| 2. | George, J. Klir. and Yuan, B., "Fuzzy sets and Fuzzy logic, Theory and Applications", Prentice Hall of India Pvt. Ltd., 1997. |
| 3. | <i>Gross, D., Shortle J. F., Thompson, J.M., and Harris, C. M., "Fundamentals of Queueing Theory", 4th Edition, John Wiley, 2014.</i> |
| 4. | Johnson, R.A., Miller, I and Freund J., Miller and Freunds "Probability and Statistics for Engineers", Pearson Education, Asia, 8 th Edition, 2015. |

| 5. | Taha, H.A., "Operations Research: An Introduction", 9 th Edition, Pearson Education, Asia, |
|----|---|
| | NewDelhi, 2016. |

| 17AEPC02 | ADVANCED DIGITAL SYSTEM DESIGN | L | Т | Р | С | |
|----------|--------------------------------|---|---|---|---|--|
| | | | | | | |

| OBJECT • • | TIVES | | | | | <u> </u> |
|---|------------------------------|---|--------------------|------------------------|-----------------------|---------------------|
| | | • | | | | |
| • | To ana | yze synchronous and asynchronous sequential circuits | | | | |
| | To real | ize and design hazard free circuits | | | | |
| • | | iliarize the practical issues of sequential circuit design | 1 | | | |
| | - | h knowledge about different fault diagnosis and testing method mate the performance of digital systems | IS | | | |
| | | w about timing analysis of memory and PLD | | | | |
| UNIT I | | SEQUENTIAL CIRCUIT DESIGN | | | | 9 |
| table assign | nment a | ed synchronous sequential circuits and modelling- State diagr nd reduction-Design of synchronous sequential circuits design alization using ASM | | | | |
| UNIT II | | ASYNCHRONOUS SEQUENTIAL CIRCUIT DESIGN | | | | ç |
| essential h vending ma UNIT III | achine | - data synchronizers – mixed operating mode asynchronous controller FAULT DIAGNOSIS AND TESTABILITY ALGORITH | | | - de | esigning |
| Fault table | metho | I-path sensitization method – Boolean difference method-D al compact algorithm – Fault in PLA – Test generation-DFT scl | lgor | ithm | | olerance |
| UNIT IV | 7 | SYNCHRONOUS DESIGN USING PROGRAMMABLE DEVICES | | | | 9 |
| - | | c device families – Designing a synchronous sequential circu te state machine using PLD – FPGA – Xilinx FPGA-Xilinx 40 | | sing | PLA | A/PAL - |
| UNIT V | | SYSTEM DESIGN USING VERILOG | | | | 9 |
| in Verilog Finite Stat bench -Rea | HDL - e Mach alization | ng with Verilog HDL – Logic System, Data Types and Oper Behavioural Descriptions in Verilog HDL – HDL Based Syn ines– structural modeling – compilation and simulation of n of combinational and sequential circuits using Verilog – Re e – serial adder – Multiplier- Divider – Design of simple micro | thes Ve egis | sis – rilog ters | Synt g cod – co | thesis o le –Tes |
| | | TOTAL : 45 PER | RIC | DS | | |
| OUTCO | MEC. | | | | | |

| ٠ | Analyze and design sequential digital circuits |
|------|---|
| • | Identify the requirements and specifications of the system required for a given application |
| ٠ | Identify the fault diagnosis. |
| • | Realize and design hazard free circuits. |
| • | Design the logic system using VHDL |
| REFE | RENCES: |
| 1. | C. H.Roth Jr and L.L.Kinney, "Fundamentals of Logic Design" Cengage Learning ,2004 |
| 2. | M.D.Ciletti, "Modeling, Synthesis and Rapid Prototyping with the Verilog HDL", Prentice Hall, 1999. |
| 3. | M.G.Arnold, "Verilog Digital – Computer Design", Prentice Hall (PTR), 1999. |
| 4. | N. N. Biswas "Logic Design Theory" Prentice Hall of India, 2001 |
| 5. | P. K.Lala "Digital system Design using PLD" B S Publications, 2003 |
| 6. | P.KLala "Fault Tolerant and Fault Testable Hardware Design" B S Publications,2002 |
| 7. | S. Palnitkar, "Verilog HDL – A Guide to Digital Design and Synthesis", Pearson, 2003. |

17AEPC03

ADVANCED DIGITAL SIGNAL PROCESSING

OBJECTIVES:

| • | To get in-depth knowledge about Discrete-time signal transforms. |
|---|--|
| • | To analyse the Power spectrum estimation. |
| • | To learn DSP architectures which are of importance in the areas of signal processing, control and communications |
| • | To understand digital filter design and optimal filtering technique. |
| • | To analyse different multi-rate digital signal processing technique. |
| | |

UNIT I

DISCRETE RANDOM SIGNAL PROCESSING

12

12

12

12

Wide sense stationary process – Ergodic process – Mean – Variance - Auto-correlation and Autocovariance matrix - Properties - Weiner Khintchine relation - Power spectral density – filtering random process, Spectral Factorization Theorem–Finite Data records, Simulation of uniformly distributed/Gaussian distributed white noise – Simulation of Sine wave mixed with Additive White Gaussian Noise.

UNIT II

SPECTRUM ESTIMATION

Bias and Consistency of estimators - Non-Parametric methods - Correlation method - Co-variance estimator - Performance analysis of estimators – Unbiased consistent estimators - Periodogram estimator - Barlett spectrum estimation - Welch estimation.

UNIT III LINEAR ESTIMATION AND PREDICTION

Model based approach - AR, MA, ARMA Signal modeling - Parameter estimation using Yule-Walker method - Maximum likelihood criterion - Efficiency of estimator - Least mean squared error criterion – Wiener filter - Discrete Wiener Hoff equations – Mean square error.

UNIT IV ADAPTIVE FILTERS

Recursive estimators - Kalman filter - Linear prediction – Forward prediction and Backward prediction, Prediction error - Whitening filter, Inverse filter - Levinson recursion, Lattice realization, Levinson recursion algorithm for solving Toeplitz system of equations.

UNIT V

MULTIRATE DIGITAL SIGNAL PROCESSING

12

FIR Adaptive filters - Newton's steepest descent method - Adaptive filters based on steepest descent method - Widrow Hoff LMS Adaptive algorithm - Adaptive channel equalization - Adaptive echo canceller - Adaptive noise cancellation - RLS Adaptive filters - Exponentially weighted RLS -

Sliding window RLS - Simplified IIR LMS Adaptive filter.

TOTAL45+15: 60 PERIODS

OUTCOMES:

| • | Exposed to different discrete signal processing methods. |
|---|---|
| • | Understanding different spectral estimation techniques. |
| • | Apply linear estimation techniques and linear prediction. |
| • | To design adaptive filters for a given application. |
| • | To design multirate DSP systems. |

REFERENCES:

| 1. | J. G. Proakis, D.G. Manolakis, "Digital Signal Processing", Prentice Hall of India, New Delhi, 2005. |
|----|--|
| 2. | M. H. Hayes, "Statistical Digital Signal Processing and Modeling", John Wiley and Sons In, New York, 2006. |
| 3. | P. P. Vaidyanathan, "Multirate Systems and Filter Banks", Prentice Hall, 1992. |
| 4. | S. Kay," Modern spectrum Estimation theory and application", Prentice Hall, Englehood Cliffs, NJ1988. |
| 5. | S. Haykin, "Adaptive Filter Theory", Prentice Hall, Englehood Cliffs, NJ1986. |
| 6. | S. J. Orfanidis, "Optimum Signal Processing ", McGraw-Hill, 2000. |

| | 04 | EMBEDDED SYSTEM DESIGN | L | Т | Р | C |
|--|--------------------------------------|--|------------------------|----------------------|----------------|-----------------------------------|
| | | | 3 | 3 0 0 3 | | 3 |
| OBJECT | TVES | : | | | | |
| • | To lear | n the design challenges about embedded system. | | | | |
| • | To lear | n various techniques of system processor. | | | | |
| • | To out | ine various protocols. | | | | |
| • | To und | erstand different state machine and process models. | | | | |
| | | ord awareness about Hardware and software design architors with real time examples. | tectu | re fo | or er | nbedded |
| UNIT I | | EMBEDDED SYSTEM OVERVIEW | | | | 9 |
| | gy, RT | m Overview, Design Challenges – Optimizing Desi -Level Combinational and Sequential Components, Optim s. | - | | | Design Single- |
| UNIT II | | GENERAL AND SINGLE PURPOSE PROCES | SO | R | | 9 |
| Counters an Concepts. | | hdog Timer, UART, LCD Controllers and Analog-to-Digita BUS STRUCTURES | l Coi | nvert | ers, | Memory |
| Basic Proto Arbitration | ocol Co , Serial | Protocols, I2C, CAN and USB, Parallel Protocols – PCI and Bluetooth, IEEE 802.11. | | | | sed I/O, |
| | 7 | STATE MACHINE AND CONCURRENT PROCESS MODELS | | | | 9 |
| UNIT IV | | I ROCESS MODELS | | | | |
| Basic State Sequential Communic Systems, | Progra ation a Autom | ne Model, Finite-State Machine with Data path Model, Captu mming Language, Program-State Machine Model, Concu mong Processes, Synchronization among processes, Datafla ation: Synthesis, Verification : Hardware/Software Co ty Cores, Design Process Models. | rrent ow N | Pro Mode | ocess el, R | Model, eal-time |
| Basic State Sequential Communic Systems, | Progra ation a Autom | ne Model, Finite-State Machine with Data path Model, Captu mming Language, Program-State Machine Model, Concu mong Processes, Synchronization among processes, Datafle ation: Synthesis, Verification : Hardware/Software Co | rrent ow N | Pro Mode | ocess el, R | Model, eal-time Reuse: |
| Basic State Sequential Communic Systems, Intellectual UNIT V Compilatio | Progra ation a Autom Proper | ne Model, Finite-State Machine with Data path Model, Captur mming Language, Program-State Machine Model, Concur mong Processes, Synchronization among processes, Dataffa ation: Synthesis, Verification : Hardware/Software Co ty Cores, Design Process Models. EMBEDDED SOFTWARE DEVELOPMENT | rrent ow M o-Sin | Pro Mode nulat | ion, | Model, eal-time Reuse: 9 |

| | TOTAL: 45 PERIODS |
|------|--|
| OUTC | COMES: |
| ٠ | Discuss design challenges and various architecture of embedded system. |
| • | Analyse the different Embedded Processors |
| • | Analyse the real time characteristics of embedded processors. |
| • | Discuss state machine and design process models |
| • | Outline embedded software development tools and RTOS |
| REFE | RENCES: |
| 1. | B.P. Douglas, "Real time UML, second edition: Developing efficient objects for embedded systems", 3rd Edition 1999, Pearson Education. |
| 2. | D.W. Lewis, "Fundamentals of embedded software where C and assembly meet", Pearson Education, 2002. |
| 3. | F. Vahid and T.Gwargie, "Embedded System Design", John Wiley & sons, 2002. |
| 4. | S. Heath, "Embedded System Design", Elsevier, Second Edition, 2004. |

| 7AEPC05 | MODERN COMMUNICATION TECHNIQUES | L | Т | Р | С |
|---------|------------------------------------|---|---|---|---|
| | | 3 | 0 | 0 | 3 |

OBJECTIVES:

| • | To estimate the power spectra of different modulation techniques. |
|---|--|
| • | To learn coherent and non-coherent communication. |
| • | To analyze digital modulation techniques over band limited channels. |
| • | To apply various channel coding techniques. |
| • | To apply various decoding algorithm. |
| | |

UNIT I POWER SPECTRUM AND COMMUNICATION OVER MEMORYLESS CHANNEL

9

PSD of a Synchronous Data Pulse Stream – M–ary Markov source – Convolutionaly Coded Modulation – Continuous Phase Modulation – Scalar and Vector Communication over Memory less Channel – Detection Criteria.

UNIT II

COHERENT AND NON –COHERENT COMMUNICATION

9

Coherent Receivers – Optimum Receivers in WGN – IQ Modulation & Demodulation – Non– Coherent receivers in Random Phase Channels – M–FSK Receivers – Rayleigh and Rician Channels – Partially Coherent Receivers – DPSK – M – PSK – M – DPSK – BER Performance Analysis.

UNIT III BANDLIMITED CHANNELS AND DIGITAL MODULATIONS

9

Eye pattern – Demodulation in the presence of ISI and AWGN – Equalization techniques – IQ modulations – QPSK – QAM – QBOM – BER Performance Analysis – Continuous Phase Modulation – CPFM – CPFSK – MSK – OFDM

UNIT IV BLOCK CODED DIGITAL COMMUNICATION

9

9

Architecture and Performance – Binary Block Codes – Orthogonal – Bi–orthogonal – Trans– orthogonal – Shannon's Channel Coding Theorem – Channel Capacity – Matched Filter – Concepts of Spread Spectrum Communication – Coded BPSK and DPSK Demodulators – Linear Block Codes – Hamming–Golay Cyclic – BCH – Reed– Solomon Codes

| UNIT V | CONVOLUTIONAL CODED DIGITAL | |
|--------|-----------------------------|--|
| | COMMUNICATION | |

Representation of Codes using Polynomial – State Diagram – Tree Diagram and Trellis Diagram – Decoding Techniques using Maximum Likelihood – Viterbi Algorithm – Sequential and Threshold

methods – Error probability performance for BPSK and Viterbi Algorithm – Turbo Coding

TOTAL : 45 PERIODS

OUTCOMES:

| • | Discuss various power spectra of communication channels. |
|------|--|
| • | Discuss coherent and non-coherent communication. |
| • | Discuss various digital modulation schemes. |
| • | Discuss various coding techniques. |
| • | Design different coding methods. |
| REFE | RENCES: |

REFERENCES:

| 1. | Simon M. K., Hinedi S. M. and Lindsey W. C., "Digital Communication Techniques, Signaling and Detection", Prentice Hall India, 1995. |
|----|---|
| 2. | S. Haykin, "Digital communications", John Wiley and Sons, 1998. |
| 3. | W. Tomasi, "Advanced Electronic Communication Systems", 4th Edition, Pearson Education, 1998. |
| 4. | Lathi B. P., "Modern Digital and Analog Communication Systems", 3rd Edition, Oxford University Press, 1998. |

| 17AEF | PC06 | EMBEDDED SYSTEM DESIGN LABORATORY | L | Т | Р | C |
|--------|--|--|------|-------|-------|-----------|
| | | (| 0 | 0 | 4 | 2 |
| OBJE | CTIVES | : | | | | |
| • | To ana | yze Synchronous and Asynchronous sequential circuits. | | | | |
| • | To dest | gn system using 8086 and 8051 Microcontroller. | | | | |
| ٠ | To stud | y different interfaces using embedded Microcontroller. | | | | |
| • | To desi | gn and analysis of real time signal processing system. | | | | |
| • | To imp | lement various equalization and coding technique. | | | | |
| LIST (| OF EXP | ERIMENTS: | | | | |
| 1. | System 8086. | design using PIC, MSP430, 51 Microcontroller and 16- bi | it I | Лісі | opro | |
| 2. | Study | of different interfaces (using embedded microcontroller). | | | | |
| 3. | Implei | nentation of Adaptive Filters and multistage multirate system in | n D | SP | Proc | essor. |
| 4. | Simula | tion of QMF using Simulation Packages. | | | | |
| 5. | Study | of 32 bit ARM7 microcontroller RTOS and its application | | | | |
| 6. | Testin | g RTOS environment and system programming | | | | |
| 7. | Design | ing of wireless sensor network using embedded systems | | | | |
| 8. | - | | qui | sitio | on ar | nd signal |
| 9. | - | | e de | efine | ed ra | dio. |
| | | TOTAL: 60 PER | ΙΟ | DS | | |
| OUTC | OMES: | i | | | | |
| • | LABORATORY004200420042004200420042004200420042004200420042004200421004100410041004100410001< | | | | | |
| • | Simul | ate QMF. | | | | |
| • | Utilize | ARM with FPGA | | | | |
| • | Desig | and analyze of real time signal processing system. | | | | |
| • | Imple | nent various coding technique. | | | | |

SEMESTER -II

| 17AEP(| C 07 | SOFT COMPUTING AND OPTIMIZATION TECHNIQUES | L | T | Р | C |
|---------------------------|---|---|----------------|------|----------------|----------|
| | | | 4 | 0 | 0 | 4 |
| OBJEC | TIVES | : | 1 | | | |
| • | To lear | n various Soft computing frameworks. | | | | |
| • | • To familiarizes with the design of various neural networks. | | | | | |
| • | To und | erstand the concept of fuzzy logic. | | | | |
| • | To gain | n insight onto Neuro Fuzzy modelling and control. | | | | |
| • | To gain | h knowledge in conventional optimization techniques. | | | | |
| • | To und | erstand the various evolutionary optimization techniques | | | | |
| UNIT I | | NEURAL NETWORKS | | | | 9 |
| UNIT I Fuzzy Se | [ets – O d Fuzzy | Organizing map, Adaptive Resonance Architectures, Hopfie FUZZY LOGIC perations on Fuzzy Sets – Fuzzy Relations – Members r Reasoning – Fuzzy Inference Systems – Fuzzy Exper- | hip | Fun | ctior | • |
| UNIT I | | NEURO-FUZZY MODELING | | | | 9 |
| and Regr | ression ' | Fuzzy Inference Systems – Coactive Neuro-Fuzzy Mode Trees – Data Clustering Algorithms – Rule base Struc trol – Case Studies. | - | | | |
| UNIT I | V | CONVENTIONAL OPTIMIZATION TECHNIQUES | | | | 9 |
| Unconstra conjugate | ained op gradien | ptimization techniques, Statement of an optimization pro otimization-gradient search method-Gradient of a function t, Newton's Method, Marquardt Method, Constrained opti- ng, Interior penalty function method, external penalty function | n, st imiza | eepe | est g 1 —se | gradient |

| UNIT V | r | EVOLUTIONARY OPTIMIZATION TECHNIQUES | | 9 |
|------------------------|-------------|---|-----------|----------------|
| Genetic a hypothesi | U | n - working principle, Basic operators and Terminolog lling Salesman Problem, Particle swam optimization, Ant colo | • | e |
| | | TOTAL : 45 PEI | RIOD | 5 |
| OUTCO |)MES: | | | |
| • | Imple | ement machine learning through Neural networks. | | |
| • | Devel | lop a Fuzzy expert system. | | |
| • | Under | rstand the various evolutionary optimization techniques | | |
| • | Mode | el Neuro Fuzzy system for clustering and classification. | | |
| • | Able | to use the optimization techniques to solve the real world prob | olems | |
| REFER | ENCE | S: | | |
| 1. | | . Goldberg, "Genetic Algorithms in Search, Optimization and son wesley, 1989. | l Machi | ne Learning ", |
| 2. | | J. Klir and B.Yuan, "Fuzzy Sets and Fuzzy lications",Prentice Hall, 1995. | Logic- | Theory and |
| 3. | | Freeman and D. M. Skapura, "Neural Networks Algorithn gramming Techniques", Pearson Edn., 2003. | ns, App | lications, and |
| 4. | | Jang, C.T. Sun, E. Mizutani, "Neuro-Fuzzy and Soft Computing, 2003. | uting", | Prentice-Hall |
| 5. | <i>M. M</i> | Ielanie, "An Introduction to Genetic Algorithm", Prentice Ha | ull, 1998 | |
| 6. | | Haykins, "Neural Networks: A Comprehensive Foundati national Inc, 1999. | ion", I | Prentice Hall |
| 7. | | . Rao, "Engineering optimization Theory and practice", . Fourth Edition, 2009 | John W | /iley & sons, |
| 8. | T. J.1 | Ross, "Fuzzy Logic with Engineering Applications", McGraw | -Hill, 1 | 997. |
| 9. | | ao, V. J. Savsani, "Mechanical Design Optimization Using Ad miques", Springer ,2012. | dvancea | Optimization |

| 17AEP(| C 08 | VLSI SYSTEM DESIGN | L | Т | Р | С | |
|---|---|--|------|-------|-------|------------------|--|
| | | | 3 | 0 | 0 | 3 | |
| OBJEC | TIVES | : | | | | | |
| • | To study the design flow of different types of ASIC. | | | | | | |
| To familiarize the different types of programming technologies and logic de | | | dev | ices. | | | |
| ٠ | | | | | | | |
| • | To gain knowledge about partitioning, floor planning, placement and rout circuit extraction of ASIC | | | outi | ng ir | ncluding | |
| • | To ana | lyse the synthesis, Simulation and testing of systems. | | | | | |
| • | To und | erstand the design issues of SOC. | | | | | |
| • | To know about different high performance algorithms and its applications in ASICs. | | | | | | |
| UNIT I OVERVIEW OF ASIC AND PLD | | 9 | | | | | |
| | | RAM – EPROM and EEPROM technology, Programmable Lo LA –PAL. Gate Arrays – CPLDs and FPGAs | ogic | Dev | vices | : ROM | |
| UNIT II | [| ASIC PHYSICAL DESIGN | | | | 9 | |
| • • | floor pl | partitioning - partitioning methods – interconnect delay mode anning - placement – Routing: global routing - detailed routin DRC. | | | | | |
| UNIT II | II | LOGIC SYNTHESIS, SIMULATION AND TESTING | | | | 9 | |
| PLA tools | s -EDIF- | Logic Synthesis - Half gate ASIC -Schematic entry - Low lev CFI design representation. Verilog and logic synthesis -VHD on -boundary scan test - fault simulation - automatic test patter | L ar | id lo | gic s | ynthesis | |
| UNIT I | V | FIELD PROGRAMMABLE GATE ARRAYS | | | | 9 | |
| | - | GA Physical Design Tools -Technology mapping - Placement c Synthesis - Controller/Data path synthesis - Logic minimiza | | | ng - | Registe | |
| × × | | | | | | | |
| UNIT V | τ | SOC DESIGN | | | | ç | |
| UNIT V System-O Concepts SoCs as | n-Chip of Bus- case st | SOC DESIGN Design - SoC Design Flow, Platform-based and IP based Based Communication Architectures. High performance alg udies: Canonical Signed Digit Arithmetic, Knowledge C netic, High performance digital filters for sigma-delta ADC. | gori | hms | for | s, Basi ASICs | |

| | TOTAL : 45 PERIODS |
|------|---|
| OUTC | OMES: |
| ٠ | Apply different high performance algorithms in ASICs. |
| • | Be familiar the different types of programming technologies and logic devices. |
| • | Analyze the synthesis, Simulation and testing of systems. |
| • | Have the knowledge of FPGA. |
| • | Discuss the design issues of SOC. |
| REFE | RENCES: |
| 1. | D.A.Hodges, "Analysis and Design of Digital Integrated Circuits (3/e)/, MGH, 2004. |
| 2. | H.Gerez, "Algorithms for VLSI Design Automation", John Wiley, 1999. |
| 3. | J. M. Rabaey, "Digital Integrated Circuit Design Perspective (2/e)", PHI, 2003 |
| 4. | M.J.S. Smith, "Application Specific Integrated Circuits", Pearson, 2003 |
| 5. | J. O.Field, R.Dorf, "Field Programmable Gate Arrays", John Wiley& Sons, Newyork, 1995. |
| 6. | P.K.Chan& S. Mourad, "Digital Design using Field Programmable Gate Array", Prentice Hal, 1994. |
| 7. | S. Pasricha and NikilDutt, "On-Chip Communication Architectures System on Chip Interconnect", Elsevier, 2008 |
| 8. | S.Trimberger, "Field Programmable Gate Array Technology", Kluwer Academic Pub, 1994. |
| 9. | S.Brown, R.Francis, J.Rose, Z.Vransic, "Field Programmable GateArray", BS, 2007. |

3 3 0 **OBJECTIVES:** To acquire the knowledge about system specification and modelling. • • To estimate the hardware/software partitioning. • To study the different technical aspects about prototyping and emulation. • To learn the hardware/software co-synthesis. • To verify and design various system level specification languages. UNIT I SYSTEM SPECIFICATION AND MODELLING 9 Embedded Systems, Hardware/Software Co-Design, Co-Design for System Specification and Modeling, Co-Design for Heterogeneous Implementation - Single-Processor Architectures with one ASIC and many ASICs, Multi-Processor Architectures, Comparison of Co- Design Approaches, Models of Computation, Requirements for Embedded System Specification. UNIT II 9 HARDWARE / SOFTWARE PARTITIONING The Hardware/Software Partitioning Problem, Hardware-Software Cost Estimation, Generation of the Partitioning Graph, Formulation of the HW/SW Partitioning Problem, Optimization, HW/SW Partitioning based on Heuristic Scheduling, HW/SW Partitioning based on Genetic Algorithms. **UNIT III** HARDWARE / SOFTWARE CO-SYNTHESIS 9 The Co-Synthesis Problem, State-Transition Graph, Refinement and Controller Generation, Co-Synthesis Algorithm for Distributed System- Case Studies with any one application. **UNIT IV PROTOTYPING AND EMULATION** 9 Introduction, Prototyping and Emulation Techniques, Prototyping and Emulation Environments, Future Developments in Emulation and Prototyping, Target Architecture- Architecture Specialization Techniques, System Communication Infrastructure, Target Architectures and Application System Classes, Architectures for Control-Dominated Systems, Architectures for Data-Dominated Systems ,Mixed Systems and Less Specialized Systems 9 UNIT V **DESIGN SPECIFICATION AND VERIFICATION** Concurrency, Coordinating Concurrent Computations, Interfacing Components, Verification ,Languages for System-Level Specification and Design System-Level Specification ,Design Representation for System Level Synthesis, System Level Specification Languages, Heterogeneous Specification and Multi-Language Co- simulation. **TOTAL: 45 PERIODS**

HARDWARE - SOFTWARE CO-DESIGN

L Т Р

0

С

17AEPC09

| OUTC | OMES: |
|-------|---|
| • | Design of system specification and modelling. |
| • | Assess prototyping and emulation techniques. |
| • | Outline various hardware and software partitioning problem. |
| • | Compare hardware / software co-synthesis. |
| • | Formulate the design specification and validate its functionality by simulation. |
| REFER | RENCES: |
| 1. | G. D.Micheli, R. E. Morgon, "Reading in Hardware/Software Co-Design" Kaufmann Publishers,2001. |
| 2. | J. Staunstrup, W. Wolf, "Hardware/Software Co-Design: Principles and Practice", Kluwer Academic Pub, 1997. |
| 3. | <i>R. Niemann</i> , <i>"Hardware/Software Co-Design for Data Flow Dominated Embedded Systems", Kluwer Academic Pub, 1998.</i> |

| 17AEI | PC10 | INTERNET OF THINGS | L | Т | Р | С | | |
|------------------|-------------------------|---|-------|-------|-------|-----------|--|--|
| | | | 3 | 0 | 0 | 3 | | |
| OBJE | CTIVES | : | | | | | | |
| ٠ | To und | lerstand the fundamentals of Internet of Things | | | | | | |
| ٠ | To lear | ut the basics of IOT protocols | | | | | | |
| ٠ | To bui | a small low cost embedded system using Raspberry Pi. | | | | | | |
| ٠ | To lear | To learn about the basics of IOT architecture. | | | | | | |
| ٠ | To app | ly the concept of Internet of Things in the real world scenario | | | | | | |
| UNIT | I | ΙΝΤRODUCTION ΤΟ ΙοΤ | | | | 9 | | |
| 1 . | | plates - Domain Specific IoTs - IoT and M2M - IoT Syste G- IoT Platforms Design Methodology | m N | Iana | igem | ent with | | |
| UNIT | II | IoT ARCHITECTURE | | | | 9 | | |
| referenc | e architec | | nicat | ion | mod | el - IoT | | |
| UNIT | III | IoT PROTOCOLS | | | | 9 | | |
| Protoco | ls – Unifi | lization for IoT – Efforts – M2M and WSN Protocols – ed Data Standards – Protocols – IEEE 802.15.4 – BACNet re – Network layer – 6LowPAN - CoAP - Security | | | | | | |
| UNIT | IV | BUILDING I0T WITH RASPBERRY PI&ARDUINO | | | | 9 | | |
| Devices | & Endpo | h RASPERRY PI- IoT Systems - Logical Design using Py ints - IoT Device -Building blocks -Raspberry Pi -Board - Lir faces -Programming Raspberry Pi with Python - Other IoT Pl | nux (| on R | aspb | erry Pi - | | |
| UNIT | V | SIMULATION OF DEVICES | | | | 9 | | |
| Comme Softwar | rcial build e & Mana | constraints - Applications - Asset management, Industrial auting automation, Smart cities - participatory sensing - Data An gement Tools for IoT Cloud Storage Models & Communication b Services for IoT. | alyti | ics f | or Io | T – | | |

| | TOTAL : 45 PERIODS |
|------|---|
| OUTC | OMES: |
| • | Analyze various protocols for IoT |
| • | Develop web services to access/control IoT devices. |
| • | Design a portable IoT using Rasperry Pi |
| • | Deploy an IoT application and connect to the cloud. |
| • | Analyze applications of IoT in real time scenario |
| REFE | RENCES: |
| 1. | A. Bahga, V. Madisetti, "Internet of Things – A hands-on approach", Universities Press, 2015 |
| 2. | D. Uckelmann, M. Harrison, Michahelles, Florian (Eds), "Architecting the Internet of Things", Springer, 2011. |
| 3. | H. Zhou, "The Internet of Things in the Cloud: A Middleware Perspective", CRC Press, 2012. |
| 4. | J. Holler, V. Tsiatsis, C. Mulligan, Stamatis, Karnouskos, S. Avesand, D. Boyle, "From Machine-to-Machine to the Internet of Things - Introduction to a New Age of Intelligence", Elsevier, 2014. |
| 5. | O. Hersent, D. Boswarthick, O. Elloumi, "The Internet of Things – Key applications and Protocols", Wiley, 2012 |

| 17AEP | C11 | VLSI SYSTEM DESIGN LABORATORY | L | T | Р | C |
|--------|---------|---|-------|----|---|---|
| | | | 0 | 0 | 4 | 2 |
| OBJE | CTIVES | : | 1 | | | |
| ٠ | To ana | yze synchronous and asynchronous sequential circuits. | | | | |
| • | To desi | gn and implement ALU in FPGA using VHDL. | | | | |
| ٠ | To desi | gn ,simulate and analyze the signal integrity. | | | | |
| ٠ | To asse | ss flash controller programming - data flash with erase, verify and | fusir | ıg | | |
| • | To desi | gn sensor using simulation tools | | | | |
| LIST (| OF EXP | ERIMENTS: | | | | |
| 1. | Analys | is of Asynchronous and clocked synchronous sequential circu | uits. | | | |
| 2. | Testin | g and Fault diagnosis of VLSI circuits. | | | | |
| 3. | VHDL | /VERILOG implementation of temperature sensor. | | | | |
| 4. | Design | , Simulation and analysis of Signal Integrity. | | | | |
| 5. | VHDL | /VERILOG implementation of I2C, SPI Interfacing. | | | | |
| 6. | Design | and Implementation of ALU in FPGA using VHDL and Ver | rilog | | | |
| 7. | Model | ing of Sequential Digital system using Verilog and VHDL. | | | | |
| 8. | Flash | controller programming - data flash with erase, verify and fus | ing. | | | |
| | | TOTAL : 60 PE | RIO | DS | | |
| OUTC | OMES: | | | | | |
| • | Desig | n sensor using simulation tools. | | | | |
| • | Explai | n design, simulation and analysis of signal integrity | | | | |
| • | Demo | nstrate design of ALU in FPGA using VHDL and Verilog | | | | |
| • | Assess | flash controller programming - data flash with erase, verify and fu | using | | | |
| • | Analys | e synchronous and asynchronous sequential circuits. | | | | |

SEMESTER -III

| 17AEP | PC13 | ELECTRONIC PRODUCT DESIGN AND DEVELOPMENT | L | T | Р | С |
|--------|--|--|---|---|---|---|
| | | | 3 | 0 | 0 | 3 |
| OBJEC | TIVE | 5: | | | | |
| • | To learn the electronic product design and development stages. | | | | | |
| • | To apply fundamentals of PCB and PCB design. | | | | | |
| • | To test and debug hardware/software design. | | | | | |
| • | To test different electronic products. | | | | | |
| • | To learn different types of standards. | | | | | |
| UNIT I | | PRODUCT DESIGN AND DEVELOPMENT | | | | 9 |

Introduction, Product development basics, Product development stages, Identification of the customer requirements, Designing the product ,Techno-commercial feasibility of a product, Pilot production batch, Product assessment, Availability, Screening test of component, redundancy, Effects of environmental conditions on reliability, Comparison between repairable and non-repairable systems, Failure rates of electronic components, Ergonomic and aesthetic design considerations.

UNIT II FUNDAMENTALS OF PCB

Introduction to PCBs, Layout, Issues related to PCB size, Interconnection parameters, Recommendations for Power and ground traces routing, PCB design for digital circuits, Noise due to ground and supply line, Grounds, Returns and Shields, PCB design rules for analog circuits, Design issues related to supply and ground conductors, Multilayer Boards, Component assembly techniques, Testing of assembled PCBs, Board layout checklist, Bare board testing, Testing of multilayer PCB, Compare of PCBs.

UNIT III

PCB DESIGN

Introduction, Computer-aided design, Automation in design, Soldering techniques, Soldering testing, Packages for semiconductor devices and ICs, Reliability issues in ICs, Parastic elements, High-speed PCBs and parasitic elements, PCB designing for microprocessor-based circuits, High speed PCB design, Design consideration in high speed PCBs, Component mounting under vibration ,SMDs, Cable.

| UNIT IV | HARDWARE, SOFTWARE DESIGN AND |
|---------|-------------------------------|
| | TESTING METHODS |

9

9

Introduction, Logic analyzer, uses of logic analyze, Oscilloscope Probes, Signal integrity, Use and limitation of Different types of analysis, SPICE, Monte-Carlo analysis, evolution of virtual

instrumentation. Introduction, Phases of software design, Goals of software design, Design of Structured program, Testing and debugging of program, Algorithmic state machine, Finite state machines, Selection of language for software development, Assemblers, Compilers, Simulators, Emulators.

UNIT V ELECTRONIC PRODUCT TESTING

9

Introduction, Environmental testing, Temperature testing, Thermal modelling of components, Humidity testing, Electrical overstress testing, Altitude testing, Special testing, Environmental test chambers and rooms, Various test on enclosures, EMI and EMC related testing, EMC and Compliance, Conducted emission test using time domain principle, Radiated emission test, Importance of standards, Standards and Standard developing organisations, List of some standards, CE marking and certification, UL marking and certification, IEC standards, IEC safety standards: CAT standards.

TOTAL : 45 PERIODS

OUTCOMES:

| • | Design electronic products |
|-------------|--|
| • | Apply fundamentals of PCB and PCB design |
| • | Implement and Test hardware design |
| • | Model Software design and testing |
| • | Prepare product documentation |
| REFERENCES: | |
| 1 | |

| 1. | <i>R.G.Kaduskar</i> , <i>V.B.Baru</i> , <i>"Electronic Product design"</i> , 2 nd Edition, Wiley, 2011. |
|----|--|
| 2. | B.Haskell, "Portable Electronics Product design and development", Mcgraw hill publisher, 2004. |
| 3. | P.Horowitz, "The Art of Electronics", Harvard university, 2015. |
| 4. | https://www.amazon.com/Electronic-Product-Design-V-B-Kaduskar-ebook/dp/B01LZF18QV |

PROJECT WORK PHASE I

| L | T | Р | С |
|---|---|----|---|
| 0 | 0 | 12 | 6 |

OBJECTIVES: • To develop the ability to solve a specific problem right from its identification and literature review till the successful solution of the same.

• To train the students in preparing project reports and to face reviews and viva voce examination.

The dissertation / project topic should be selected / chosen to ensure the satisfaction of the urgent

need to establish a direct link between education, national development and productivity and thus

reduce the gap between the world of work and the world of study. The dissertation should have the following

- Relevance to social needs of society
- Relevance to value addition to existing facilities in the institute
- Relevance to industry need
- Problems of national importance
- Research and development in various domain

The student should complete the following:

- Literature survey Problem Definition
- Motivation for study and Objectives
- Preliminary design / feasibility / modular approaches
- Implementation and Verification
- Report and presentation

GUIDELINES FOR DISSERTATION PHASE – I

- As per the AICTE directives, the dissertation is a year long activity, to be carried out and evaluated in two phases i.e. Phase I: July to December.
- The dissertation may be carried out preferably in-house i.e. departments laboratories and centers OR in industry allotted through departments T & P coordinator.
- After multiple interactions with guide and based on comprehensive literature survey, the student shall identify the domain and define dissertation objectives. The referred literature should preferably include IEEE/IET/IETE/Springer/Science Direct/ACM journals in the areas of Computing and Processing (Hardware and Software), Circuits-Devices and Systems, Communication-Networking and Security, Robotics

| • | In case of Industry sponsored projects, to product catalogues should be referred and reported. Student is expected to detail out specific critical issues involved in design and distribution, and submit the proposal with Phase – I deliverables: A document rep survey, detailed objectives, project spec design, proof of concept/functionality, progress. Phase – I evaluation: A committee specialization shall assess the progress/pe | implementation and phase wise work in a month from the date of registration. Fort comprising of summary of literature cifications, paper and/or computer aided part results, A record of continuous |
|--------|---|---|
| | | TOTAL : 180 PERIODS |
| OUTCOM | IES: | |
| - | Ability to synthesize knowledge and skills p study and execution of new technical proble | |
| | Capable to select from different methodolog produce a suitable research design, and justi | |
| • 1 | Ability to present the findings of their technic | ical solution in a written report. |

SEMESTER- IV

| 17AEEF | 215 PROJECT WORK PHASE II | L | Т | Р | С | | |
|--|--|-------|----|--------|--------|--|--|
| | | 0 | 0 | 24 | 12 | | |
| OBJEC | OBJECTIVES: | | | | | | |
| • To develop the ability to solve a specific problem right from its identification and literature review till the successful solution of the same. | | | | | | | |
| • | To train the students in preparing project reports and to face re- | views | an | d viva | a voce | | |

The dissertation / project topic should be selected / chosen to ensure the satisfaction of the urgent

need to establish a direct link between education, national development and productivity and thus

reduce the gap between the world of work and the world of study. The dissertation should have the following

- Relevance to social needs of society
- Relevance to value addition to existing facilities in the institute
- Relevance to industry need

examination.

- Problems of national importance
- Research and development in various domain

The student should complete the following:

- Literature survey Problem Definition
- Motivation for study and Objectives
- Preliminary design / feasibility / modular approaches
- Implementation and Verification
- Report and presentation

The dissertation stage II is based on a report prepared by the students on dissertation allotted to

them. It may be based on:

- Experimental verification / Proof of concept.
- Design, fabrication, testing of Communication System.
- The viva-voce examination will be based on the above report and work.

GUIDELINES FOR DISSERTATION PHASE – II

• As per the AICTE directives, the dissertation is a yearlong activity, to be carried out and evaluated in two phases i.e. Phase – I: July to December and Phase – II: January to June .

- The dissertation may be carried out preferably in-house i.e. departments laboratories and centers OR in industry allotted through departments T & P coordinator.
- After multiple interactions with guide and based on comprehensive literature survey, the student shall identify the domain and define dissertation objectives. The referred literature should preferably include IEEE/IET/IETE/Springer/Science Direct/ACM journals in the areas of Computing and Processing (Hardware and Software), Circuits-Devices and Systems, Communication-Networking and Security, Robotics and Control Systems, Signal Processing and Analysis and any other related domain. In case of Industry sponsored projects, the relevant application notes, while papers, product catalogues should be referred and reported.
- Student is expected to detail out specifications, methodology, resources required, critical issues involved in design and implementation and phase wise work distribution, and submit the proposal within a month from the date of registration.
- Phase I deliverables: A document report comprising of summary of literature survey, detailed objectives, project specifications, paper and/or computer aided design, proof of concept/functionality, part results, A record of continuous progress.
- Phase I evaluation: A committee comprising of guides of respective specialization shall assess the progress/performance of the student based on report, presentation and Q & A. In case of unsatisfactory performance, committee may recommend repeating the Phase-I work.
- During phase II, student is expected to exert on design, development and testing of the proposed work as per the schedule. Accomplished results/contributions/innovations should be published in terms of research papers in reputed journals or reviewed focused conferences or IP/Patents.
- Phase II deliverables: A dissertation report as per the specified format, developed system in the form of hardware and/or software, A record of continuous progress.
- Phase II evaluation: Guide along with appointed external examiner shall assess the progress/performance of the student based on report, presentation and Q & A. In case of unsatisfactory performance, committee may recommend for extension or repeating the work.

TOTAL : 360 PERIODS

| OUTC | OUTCOMES: | | | | | | |
|------|--|--|--|--|--|--|--|
| • | Ability to synthesize knowledge and skills previously gained and applied to an in-depth study and execution of new technical problem | | | | | | |
| • | Capable to select from different methodologies, methods and forms of analysis to produce a suitable research design, and justify their design. | | | | | | |
| • | Ability to present the findings of their technical solution in a written report. | | | | | | |
| • | Presenting the work in International/ National conference or reputed journals. | | | | | | |

PROFESSIONAL ELECTIVES (PE)

SEMESTER-I

ELECTIVE I

| 17AEPE01 | DIGITAL CONTROL ENGINEERING | L | Т | Р | С | |
|---|---|--|--|-------------------------|---------------------------------------|--|
| | | 3 | 0 | 0 | 3 | |
| OBJECTI | VES: | - | | | | |
| • To | • To learn the principles of PI,PD,PID controllers | | | | | |
| • To | analyse time and frequency response of discrete time control | system | | | | |
| • To | be familiar in digital control algorithms. | | | | | |
| • To | get basic knowledge to implement PID control algorithms. | | | | | |
| • To | learn the basic DSP in control system. | | | | | |
| UNIT I | CONTROLLERS IN FEEDBACK SYSTEMS | | | | 9 | |
| | BASIC DIGITAL SIGNAL PROCESSING IN | CONI | ROL | | ç | |
| UNIT II | SYSTEMS | | | ticalı | | |
| Sampling the | SYSTEMS orem, quantization, aliasing and quantization error, hold opera and hold, zero and first order hold, factors limiting the c | tion, m | athema | | mode | |
| Sampling the of sample a | SYSTEMS orem, quantization, aliasing and quantization error, hold opera and hold, zero and first order hold, factors limiting the c | tion, m hoice | athema of sam | pling | mode rate | |
| Sampling the of sample a reconstruction UNIT III Difference eq frequency re- stability test, | SYSTEMS orem, quantization, aliasing and quantization error, hold opera nd hold, zero and first order hold, factors limiting the c | tion, m hoice L SYS ransfer | athema of sam STEM functio ol syste | pling n, tim ems, | rate, 9 ne and Jury's | |
| Sampling the of sample a reconstruction UNIT III Difference eq frequency re- stability test, | SYSTEMS orem, quantization, aliasing and quantization error, hold operated hold, zero and first order hold, factors limiting the control MODELING OF SAMPLED DATA CONTROL uation description, Z-transform method of description, pulse to sponse of discrete time control systems, stability of digital state space description, first companion, second co | tion, m hoice L SYS ransfer l contro Jordan | athema of sam STEM functio ol syste | pling n, tim ems, | mode rate 9 ne anc Jury's | |

9 ALGORITHMS Algorithm development of PID control algorithms, standard programmes for microcontroller implementation, finite word length effects, choice of data acquisition systems, microcontroller based temperature control systems, microcontroller based motor speed control systems, DSP implementation of motor control system. **TOTAL: 45 PERIODS OUTCOMES:** Describe continuous time and discrete time controllers analytically. • Define and state basic analog to digital and digital to analog conversion principles. • Analyze sampled data control system in time and frequency domains. • • Design simple PI, PD, PID continuous and digital controllers. Develop schemes for practical implementation of temperature and motor control systems. **REFERENCES:** J. J. D'Azzo, "Constantive Houpios, Linear Control System Analysis and Design", Mc 1. Graw Hill, 1995. K. J. Ayala, "The 8051 Microcontroller- Architecture, Programming and Applications", 2. Penram International, 2nd Edition, 1996. M.Gopal, "Digital Control and Static Variable Methods", Tata McGraw Hill, New Delhi, 3. 1997.

UNIT V PRACTICAL ASPECTS OF DIGITAL CONTROL

| 17AEPE02 | | COMPUTER ARCHITECTURE | L | Т | Р | С |
|---|---|--|--|--|--|--|
| | | | 3 | 0 | 0 | 3 |
| OBJEC | CTIVE | ES: | | 1 | | |
| • To understand the difference between pipeline and parallel processing concepts | | | | | | |
| ٠ | • To study various types of processor architectures and the importance of architectures | | | | | |
| • | To st | udy Memory Optimization and Technique. | | | | |
| • | To le | earn issues related to memory architecture. | | | | |
| • | To st | udy Memory Architectures | | | | |
| UNIT I | | COMPUTER DESIGN AND PERFORMANCE MEASURES | | | | 9 |
| | 1 0 0 0 | | | | | |
| | ow arch | D architectures – Multithreaded architectures – Stanford Dash n hitectures - Performance Measures PARALLEL PROCESSING, PIPELINING AND | | | sor – 1 | |
| - Data-flo UNIT I Instructio Overcom | ow arch I on Leve ing Da | itectures - Performance Measures | ILP Pipe edicti | lining p on - Sp | proces | 9 sors - |
| - Data-flo UNIT I Instructio Overcom Multiple | ow arch I on Leve ing Da Issue P | hitectures - Performance Measures PARALLEL PROCESSING, PIPELINING AND el Parallelism and Its Exploitation - Concepts and Challenges - ta Hazards with Dynamic Scheduling – Dynamic Branch Pre | ILP Pipe edicti | lining p on - Sp | proces | 9 sors - |
| - Data-flo UNIT I Instructio Overcom Multiple UNIT I Memory | I Leve ing Da Issue P II Hierare | hitectures - Performance Measures PARALLEL PROCESSING, PIPELINING AND el Parallelism and Its Exploitation - Concepts and Challenges - ta Hazards with Dynamic Scheduling – Dynamic Branch Pre Processors - Performance and Efficiency in Advanced Multiple | Pipe edicti Issue | lining p on - Sp e Proces | proces pecula ssors | 9 sors - tion - 9 ons of |
| - Data-flo UNIT I Instructio Overcom Multiple UNIT I Memory | ow arch I on Leve ing Da Issue P II Hierard erforma | hitectures - Performance Measures PARALLEL PROCESSING, PIPELINING AND el Parallelism and Its Exploitation - Concepts and Challenges - ta Hazards with Dynamic Scheduling – Dynamic Branch Pre Processors - Performance and Efficiency in Advanced Multiple MEMORY HIERARCHY DESIGN chy - Memory Technology and Optimizations – Cache memory | Pipe edicti Issue | lining p on - Sp e Proces | proces pecula ssors | 9 sors - tion - 9 ons of |
| - Data-flo UNIT I Instructio Overcom Multiple UNIT I Memory Cache Pe UNIT I Symmetr Issues – | ow arch I on Leve ing Da Issue P II Hierard erforma V ic and Synch | Antitectures - Performance Measures PARALLEL PROCESSING, PIPELINING AND A Parallelism and Its Exploitation - Concepts and Challenges - ta Hazards with Dynamic Scheduling – Dynamic Branch Pre Processors - Performance and Efficiency in Advanced Multiple MEMORY HIERARCHY DESIGN chy - Memory Technology and Optimizations – Cache memor nce – Memory Protection and Virtual Memory - Design of Me | ILP Pipe edicti Issue ory – emory | lining p on - Sp e Proces - Optim 7 Hieran es – Pe | proces becula ssors izatio | 9 sors - tion - 9 ons of 9 nance |
| - Data-flo UNIT I Instructio Overcom Multiple UNIT I Memory Cache Pe UNIT I Symmetr Issues – Buses, cre | ow arch I on Leve ing Da Issue P II Hierard erforma V ic and Synchu ossbar | Antitectures - Performance Measures PARALLEL PROCESSING, PIPELINING AND Parallelism and Its Exploitation - Concepts and Challenges - ta Hazards with Dynamic Scheduling – Dynamic Branch Pre Processors - Performance and Efficiency in Advanced Multiple MEMORY HIERARCHY DESIGN chy - Memory Technology and Optimizations – Cache memor nce – Memory Protection and Virtual Memory - Design of Me MULTIPROCESSORS distributed shared memory architectures – Cache coherence ronization issues – Models of Memory Consistency - Interce | ILP Pipe edicti Issue ory – emory | lining p on - Sp e Proces - Optim 7 Hieran es – Pe | proces becula ssors izatio | 9 sors - tion - 9 ons of 9 nance |
| - Data-flo UNIT I Instructio Overcom Multiple UNIT I Memory Cache Pe UNIT I Symmetr Issues – Buses, cr UNIT V Software | ow arch I on Leve ing Da Issue P II Hierard erforma V ic and Synchu- ossbar V and ha | A parallelism and Its Exploitation - Concepts and Challenges - ta Hazards with Dynamic Scheduling – Dynamic Branch Pre Processors - Performance and Efficiency in Advanced Multiple MEMORY HIERARCHY DESIGN chy - Memory Technology and Optimizations – Cache memor nce – Memory Protection and Virtual Memory - Design of Me MULTIPROCESSORS distributed shared memory architectures – Cache coherence ronization issues – Models of Memory Consistency - Interc and multi-stage switches. | Pipe edicti Issue ory – emory e issu conne | lining p on - Sp e Proces - Optim / Hieran / Hieran | process becula ssors iizatic rchies erform netwo | 9 sors - tion - 9 ons of 9 nance rks - 9 |

| OUTC | OMES: |
|------|---|
| • | Have the basic fundamentals of computer design and measure the performance. |
| • | Understand pipelining and parallel processing |
| • | Explain design of memory hierarchies. |
| • | Assess Performance Issues and Synchronization issues. |
| • | Compare multicore architectures. |
| REFE | RENCES: |
| 1. | D. E. Culler, J. P.Singh, "Parallel Computing Architecture: A hardware/ software approach", Morgan Kaufmann / Elsevier, 1997. |
| 2. | D.Soudris, A. Jantsch, "Scalable Multi-core Architectures: Design Methodologies and Tools", Springer, 2012. |
| 3. | H. Briggs, "Computer Architecture and parallel processing", McGraw Hill, 1984. |
| 4. | J.L. Hennessey and D. A. Patterson, "Computer Architecture – A quantitative approach", Morgan Kaufmann / Elsevier, 4th. edition, 2007. |
| 5. | J. P. Hayes, "Computer Architecture and Organization", McGraw Hill, 3 rd Edition, 2017. |
| 6. | J.P. Shen, "Modern processor design. Fundamentals of super scalar processors", Tata McGraw Hill ,2003. |
| 7. | K. Hwang, "Advanced Computer Architecture", McGraw Hill International, 2001. |
| 8. | W. Stallings, "Computer Organization and Architecture – Designing for Performance", Pearson Education, Seventh Edition, 2006. |

| 17AEPE03 | | | VLSI DESIGN TECHNIQUES | L | Т | Р | С | |
|---|--|---------------|---|-----------|-----------|--------|-------|--|
| | | | | 3 | 0 | 0 | 3 | |
| OBJEC | TIVE | S: | | I | | | 1 | |
| • To understand the principles of MOS transistor and CMOS inverter. | | | | | | | | |
| • | To study the layout and stick diagram of combinational circuits. | | | | | | | |
| • | To stu | udy | various latches and register in logic circuits. | | | | | |
| • | To cla | assi | fy different building blocks and architecture. | | | | | |
| • | To di | scus | ss various digital systems design. | | | | | |
| UNIT I | | | OS TRANSISTOR PRINCIPLES AND CM VERTER | OS | | | 9 | |
| Secondar | y Effect MOS In | ts, F nvei | or Characteristic under Static and Dynamic Conditions Process Variations, Technology Scaling, Internet Parar rter - Static Characteristic, Dynamic Characteristic, Po | neter and | l electri | cal w | | |
| UNIT I | I | CC | OMBINATIONAL LOGIC CIRCUITS | | | | 9 | |
| | constar | nt, E | Stick diagram, Layout diagrams, Examples of combir Dynamic Logic Gates, Pass Transistor Logic, Power D | | - | - | r | |
| UNIT I | II | SE | QUENTIAL LOGIC CIRCUITS | | | 9 | | |
| | | | Registers, Dynamic Latches and Registers, Timing Is d Registers, Non bistable Sequential Circuits. | ssues, P | ipelines | , Puls | e and | |
| UNIT I | | | RITHMETIC BUILDING BLOCKS AND M RCHITECTURES | IEMO | RY | | 9 | |
| - | | | Architectures for Adders, Accumulators, Multipliers, nory Architectures, and Memory control circuits. | Barrel S | Shifters, | Spee | d and | |
| UNIT V | UNIT V INTERCONNECT AND CLOCKING STRATEGIES | | S | | 9 | | | |
| Interconn | | | eters – Capacitance, Resistance, and Inductance, Elect | | | els, T | iming | |
| classifica | tion of l | Dig | ital Systems, Synchronous Design, Self-Timed Circuit | Design. | | | | |

| OUTCO | DMES: |
|-------|--|
| • | Design digital systems using MOS transistor and invertors. |
| • | Able to learn layout, stick diagram in combinational logic circuits |
| • | Discuss various latches and registers in sequential circuits. |
| • | Discuss design methodology of arithmetic building block. |
| • | Analyze tradeoffs of the various circuit choices for each of the building block. |
| REFER | RENCES: |
| 1. | J. Baker "CMOS: Circuit Design, Layout, and Simulation, Third Edition", Wiley IEEE Press 2010. |
| 2. | J. Rabaey, A. Chandrakasan, B Nikolic, "Digital Integrated Circuits: A Design Perspective". Prentice Hall of India 2nd Edition, 2003. |
| 3. | M J Smith, "Application Specific Integrated Circuits", Addisson Wesley, 1997. |
| 4. | N.Weste, K. Eshraghian, ," Principles of CMOS VLSI Design"., Addision Wesley, 2nd Edition, 1993. |

| 17AEPE04 | | ELECTROMAGNETIC INTERFERENCE AND COMPATIBILITY | L | T | Р | C |
|--|--|--|------------------------------|-------------------|--------------|-----------------|
| | | | 3 | 0 | 0 | 3 |
| BJECT | FIVES | S: | 1 | | | |
| • To learn the basics of EMI | | | | | | |
| • | Be fan | niliar with EMI sources and problems. | | | | |
| • | • To understand solution methods in PCB. | | | | | |
| • | | cuss various measurement techniques for emission. | | | | |
| | To dis | cuss various measurement techniques for immunity. | | | | |
| NIT I | | BASIC THEORY | | | | 9 |
| zards to | human | Conducted and Radiated EMI emission and susceptibility, C s, Various issues of EMC, EMC Testing categories EMC En | | | | |
| NIT II | (| COUPLING MECHANISM | | | | 9 |
| NIT II | | EMI MITIGATION TECHNIQUES | | | | 9 |
| fectivene | ess, Cho Princij | e of Shielding and Murphy"s Law, LF Magnetic shielding, bice of Materials for H, E, and free space fields, Gasketting | and s ies fo | ealing, r Larg | PCB e sys | Level stems, |
| - | • | ble of Grounding, Isolated grounds, Grounding strateg xed signal systems, Filter types and operation, Surge prote | ection | | | |
| ounding | | | | | | 9 |
| rounding otection. NIT IV eed for S andards, NSI, FC | 7 Standar Produ CC, A | xed signal systems, Filter types and operation, Surge prote | trial en | rganiza | tions; | IEC, |
| rounding otection. NIT IV eed for S andards, NSI, FC | 7 Standar Produ CC, A lity stan | xed signal systems, Filter types and operation, Surge prote STANDARD AND REGULATION ds, Generic/General Standards for Residential and Indust ct Standards, National and International EMI Standardizi S/NZS, CISPR, BSI, CENELEC, ACEC. Electro M | trial er ing Or lagnet | rganiza ic Em | tions; | Basic IEC |

Feed through capacitors, Antennas, Current probes, MIL -STD test methods, Civilian STD test methods.

| TOTAL : | 45 | PERIODS |
|---------|-----|---------|
| | -10 | |

| | IUIAL . 45 I EKIODS |
|------|--|
| OUTC | COMES: |
| • | Able to learn basic idea about EMI and EMC. |
| ٠ | Discuss different coupling mechanism. |
| ٠ | Discuss EMI mitigation techniques. |
| ٠ | Identify Standards. |
| ٠ | Compare EMI test methods. |
| REFE | RENCES: |
| 1. | <i>B. Keiser, "Principles of Electromagnetic Compatibility", 3rd Ed, Artech house, Norwood, 1986.</i> |
| 2. | C. Paul, "Introduction to Electromagnetic Compatibility", Wiley Interscience, 2006. |
| 3. | D. Gerke and W. Kimmel, "EDN's Designer's Guide to Electromagnetic Compatibility", Elsevier Science & Technology Books, 2002. |
| 4. | Dr K. L. Kaiser, "The Electromagnetic Compatibility Handbook", CRC Press, 2005. |
| 5. | N.Violette, "Electromagnetic Compatibility", ,Published by Springer, 2013. |
| 6. | D. R. J. White, "Electromagnetic Interference and Compatibility: Electrical noise and EMI specifications Volume 1 of A Handbook Series on Electromagnetic Interference and Compatibility", Publisher-Don white consultants Original from the University of Michigan Digitized 6, 2007. |
| 7. | <i>H. W. Ott, "Electromagnetic Compatibility Engineering", John Wiley & Sons , Newyork,, 2009.</i> |
| 8. | V.P. Kodali, "Engineering Electromagnetic Compatibility", IEEE Press, Newyork, ,2001. |
| | |

PROFESSIONAL ELECTIVES (PE)

SEMESTER -II

ELECTIVE II

| | PE05 | | CA | D FOR VLS | I | L | Т | Р | С |
|--|---|--|--|--|---|--|------------|-------|--|
| | | | | | | 3 | 0 | 0 | 3 |
| BJECT | TVES | | | | | I | | | |
| • | To st | udy | arious physical desi | gn methods in V | LSI. | | | | |
| ٠ | To ur | nders | and the concepts be | nind the VLSI d | lesign rules and ro | uting tec | hnique | s. | |
| • | To us | e th | simulation techniqu | es at various lev | vels in VLSI desig | n flow | | | |
| • | To ur techn | | and the concepts of . | various algorith | ms used for floor | planning | and ro | uting | |
| ٠ | To st | udy | ardware models for | high level synth | iesis. | | | | |
| UNIT I | | IN' | RODUCTION | TO VLSI DE | SIGN FLOW | | | | 9 |
| | | | orial optimization. | | | | | | |
| • | Compact | ion, | YOUT, PLACEN Design rules, Problem oning, Circuit repres | n formulation, | Algorithms for co | nstraint g | - | ompao | 9 ction, |
| Layout C | Compact nt and p | ion, artit | | n formulation, a entation, Placen | Algorithms for co nent algorithms, F | nstraint g | - | ompao | |
| Layout C Placemer UNIT I Floor pla | Compact nt and p II anning of | ion, artit FL | Design rules, Problem oning, Circuit repres | n formulation, <i>A</i> entation, Placen G AND ROU s and floor pla | Algorithms for co nent algorithms, F TING n sizing, Types o | nstraint g artitionin | ıg. | | ction, 9 |
| Layout C Placemer UNIT I Floor pla | Compact nt and p II anning of ting, Ch | ion, artit FL conc | Design rules, Problem oning, Circuit repres OOR PLANNIN pts, Shape function | n formulation, A entation, Placen G AND ROU s and floor pla ting, Algorithm | Algorithms for co nent algorithms, F TING n sizing, Types o s for global routir | nstraint g artitionin | ıg. | | ction, 9 |
| Layout C Placemer UNIT I Floor pla Area rout UNIT I Simulatio | Compact nt and p II anning o ting, Ch V On, Ga | ion, artit FL conc anno SIN tte-le | Design rules, Problem oning, Circuit repres DOR PLANNIN pts, Shape function I routing, Global rou | n formulation, A entation, Placen G AND ROU s and floor pla ting, Algorithm D LOGIC SY simulation, | Algorithms for co nent algorithms, F TING n sizing, Types o s for global routir NTHESIS Switch-level mo | nstraint g artitionin of local r ng. | outing | prob | ction, 9 lems, 9 |
| Layout C Placemer UNIT I Floor pla Area rout UNIT I Simulatio | Compact nt and p II anning o ting, Ch V Don, Ga tional L | ion, artiti FL conc anno SIN tte-le Logic | Design rules, Problem oning, Circuit represe DOR PLANNING pts, Shape function routing, Global rou IULATION ANI | n formulation, A entation, Placen G AND ROU s and floor pla ting, Algorithm D LOGIC SY simulation, ecision Diagran | Algorithms for co nent algorithms, F TING n sizing, Types o s for global routir NTHESIS Switch-level mo | nstraint g artitionin of local r ng. | outing | prob | ction, 9 lems, 9 |
| Layout C Placemen UNIT I Floor pla Area rout UNIT I Simulatic Combina UNIT V Hardware | Compact nt and p II anning o ting, Ch V On, Ga tional L V e mode | ion, artit FL conc anno SIN tte-le cogic HIC | Design rules, Problem oning, Circuit represe DOR PLANNING pts, Shape function I routing, Global rou IULATION ANI vel modeling and Synthesis, Binary D | n formulation, A entation, Placen G AND ROU s and floor pla ting, Algorithm D LOGIC SY simulation, ecision Diagran THESIS esis, internal | Algorithms for co nent algorithms, F TING n sizing, Types o s for global routir NTHESIS Switch-level mons, Two Level Lo | nstraint g artitionin of local r ag. odeling gic Synth location, | and sesis. | prob | ction, 9 lems, 9 ation, 9 |

| OUTC | OMES: |
|-------|--|
| • | To use the simulation techniques at various levels in VLSI design flow. |
| • | Discuss the layout design rules and various placement algorithms. |
| • | Discuss the concepts of floor planning and routing. |
| • | Outline high level synthesis. |
| • | Discuss VLSI design methodology and its design automation tools. |
| REFER | RENCES: |
| 1. | N.A. Sherwani, "Algorithms for VLSI Physical Design Automation", Kluwer Academic Publishers, Third Edition, 2002. |
| 2. | S.H. Gerez, "Algorithms for VLSI Design Automation", John Wiley & Sons, 2002. |
| 3. | S.M. Sait, H.Youssef, "VLSI Physical Design automation: Theory and Practice", World scientific, 1999. |
| 4. | S.M.Rubin, "Computer Aids for VLSI Design", Addison Wesley Publishing, 1987. |

| 17AEPE06 | | | NANOELECTRONICS | L | Т | Р | С |
|--|--|---|---|---|---|---|--|
| | | · | | 3 | 0 | 0 | 3 |
| OBJEC | CTIVE | ES: | | | 1 | | |
| • | To le | earn a | and understand basic concepts of Nano electronics. | | | | |
| • | To k | now | about electronic and photonic materials. | | | | |
| • | To u | nders | stand how transistor as Nano device. | | | | |
| • | To g | ain k | nowledge about Nano Sensors. | | | | |
| ٠ | To u | nders | stand various forms of nano devices. | | | | |
| UNIT I | [| SE | MICONDUCTOR NANO DEVICES | | | | 9 |
| | nputers | : Opt | obotics and Nanomanipulation; Mechanical M tical Fibers for Nanodevices; Photochemical Molecul ased Nanodevices. | | | nodev NA-H | |
| Inallouev | | | | | | 1 | |
| UNIT I | Ι | EL | ECTRONIC AND PHOTONIC MATERIAL | | lasers: | - Oua | - |
| UNIT I Preparati cascade 1 lasers:- V | II ion – El lasers- (White I s - High | EL lectro Casca LEDs n Effi | ECTRONIC AND PHOTONIC MATERIAL oluminescent Organic materials - Laser Diodes - Quantu ade surface-emitting photonic crystal laser- Quantum d s - LEDs based on nanowires - LEDs based on nano iciency Materials for OLEDs- High Efficiency Materia | im well ot laser | s - Qua - LEDs | intum base | ntum wire |
| UNIT I Preparati- cascade 1 lasers:- V nanorods | II ion – El lasers- (White I s - High ared ph | EL lectro Casca LED n Effi oto d | ECTRONIC AND PHOTONIC MATERIAL oluminescent Organic materials - Laser Diodes - Quantu ade surface-emitting photonic crystal laser- Quantum d s - LEDs based on nanowires - LEDs based on nano iciency Materials for OLEDs- High Efficiency Materia | im well ot laser | s - Qua - LEDs | intum base | ntum wire ed or ntum |
| UNIT I Preparatic cascade l lasers:- V nanorods well infra UNIT I Thermal resistance magnetis | II ion – El lasers- (White I s - High ared ph III energy e senso sm senso | ELZ lectro Casca LEDs n Effi oto d TH 7 sen ors, e sors - | ECTRONIC AND PHOTONIC MATERIAL oluminescent Organic materials - Laser Diodes - Quantu ade surface-emitting photonic crystal laser- Quantum d s - LEDs based on nanowires - LEDs based on nano iciency Materials for OLEDs- High Efficiency Materia letectors. | im well ot laser otubes - ls for O netic se electrica | s - Qua - LEDs DLEDs ensors - il powe | e dec der ser | ntum wire ed or ntum g |
| UNIT I Preparatic cascade l lasers:- V nanorods well infra UNIT I Thermal resistance magnetis | II ion – El lasers- (White I s - High ared pho III energy e sensc sm sens Chemi | EL lectro Casca LEDs n Effi oto d TH y sen prs, e sors - cal se | ECTRONIC AND PHOTONIC MATERIAL oluminescent Organic materials - Laser Diodes - Quantu ade surface-emitting photonic crystal laser- Quantum d s - LEDs based on nanowires - LEDs based on nano iciency Materials for OLEDs- High Efficiency Materia letectors. ERMAL SENSORS sors -temperature sensors, heat sensors - Electromag electrical current sensors, electrical voltage sensors, of - Mechanical sensors - pressure sensors, gas and liquit | im well ot laser otubes - ls for O netic se electrica | s - Qua - LEDs DLEDs ensors - il powe | e dec der ser | ntum wire ed or ntum futrica sors sitior |
| UNIT I Preparati- cascade 1 lasers:- V nanorods well infra UNIT I Thermal resistance magnetis sensors - UNIT I Criteria f | II ion – El lasers- (White I s - High ared ph III energy e sense Sm sense Chemi IV for the ing pro | EL lectro Casca LEDs n Effi oto d TH y sen ors, e sors - cal so GA choid operty | ECTRONIC AND PHOTONIC MATERIAL oluminescent Organic materials - Laser Diodes - Quantu ade surface-emitting photonic crystal laser- Quantum d s - LEDs based on nanowires - LEDs based on nano iciency Materials for OLEDs- High Efficiency Materia letectors. ERMAL SENSORS sors -temperature sensors, heat sensors - Electromag electrical current sensors, electrical voltage sensors, e - Mechanical sensors - pressure sensors, gas and liqui ensors - Optical and radiation sensors. SSENSORS ce of materials - Experimental aspects – materials, pro y, sensitivity; Discussion of sensors for various gases | im well ot laser otubes - ls for O netic se electrica id flow | s - Qua - LEDs DLEDs ensors al powe sensor | - eleccer ser s, pos | ntum wire ed or ntum g trica isors sitior g ent of |
| UNIT I Preparatic cascade I lasers:- V nanorods well infra UNIT I Thermal resistance magnetis sensors - UNIT I Criteria f gas sensi | II ion – El lasers- (White I s - High ared ph ared ph III energy e sense Sm sens Chemi IV for the ing pro- | EL lectro Casca LEDs n Effi oto d TH y sen ors, e sors - cal so GA choid perty levice | ECTRONIC AND PHOTONIC MATERIAL oluminescent Organic materials - Laser Diodes - Quantu ade surface-emitting photonic crystal laser- Quantum d s - LEDs based on nanowires - LEDs based on nano iciency Materials for OLEDs- High Efficiency Materia letectors. ERMAL SENSORS sors -temperature sensors, heat sensors - Electromag electrical current sensors, electrical voltage sensors, e - Mechanical sensors - pressure sensors, gas and liqui ensors - Optical and radiation sensors. SSENSORS ce of materials - Experimental aspects – materials, pro y, sensitivity; Discussion of sensors for various gases | im well ot laser otubes - ls for O netic se electrica id flow | s - Qua - LEDs DLEDs ensors al powe sensor | - eleccer ser s, pos | ntum wire ed or ntum g trica isors sitior g ent of ed or |
| UNIT I Preparatic cascade 1 lasers:- V nanorods well infra UNIT I Thermal resistance magnetis sensors - UNIT I Criteria f gas sensi semiconce UNIT V Principle | II ion – El lasers- (White I s - High ared ph III energy e senso sm sens Chemi IV for the ing pro ductor c V es - DNA | EL lectro Casca LEDs n Effi oto d TH / sen ors, e sors - cal so GA choic perty levic BIC | ECTRONIC AND PHOTONIC MATERIAL oluminescent Organic materials - Laser Diodes - Quantu ade surface-emitting photonic crystal laser- Quantum d s - LEDs based on nanowires - LEDs based on nano iciency Materials for OLEDs- High Efficiency Materia letectors. ERMAL SENSORS sors -temperature sensors, heat sensors - Electromag electrical current sensors, electrical voltage sensors, of - Mechanical sensors - pressure sensors, gas and liqui ensors - Optical and radiation sensors. SSENSORS ce of materials - Experimental aspects – materials, pro y, sensitivity; Discussion of sensors for various gases es. | im well ot laser otubes - ls for O netic se electrica id flow | s - Qua - LEDs DLEDs ensors - al powe sensor , measu sensors | antum base - Qua - electer ser s, pos | wire ed on ntum 9 trical isors, sition 9 ent of ed on 9 |

| OUTCO | OMES: |
|-------|---|
| • | Knowledge of various materials used in nano devices. |
| • | Able to design and simulate nano device. |
| • | Exposure to the different nano sensors. |
| • | Able to design and simulate nano sensors. |
| • | To familiarize with the present research front in Nanooelectronics and to be able to critically assess future trends. |
| REFER | RENCES: |
| 1. | K.E. Drexler, "Nano systems", Wiley, 1992. |
| 2. | M.C. Petty, "Introduction to Molecular Electronics", Oxford University Press, 1995. |
| 3. | W. Ranier, "Nano Electronics and Information Technology", Wiley, Third Edition, 2012. |

| 17AEPE07 | | SENSORS AND MEASUREMENTS SYSTEMS | L | Т | Р | С |
|--|--|---|---|--|---|---|
| | | | 3 | 0 | 0 | 3 |
| OBJEC | TIVE | S: | | | | |
| • | To kn | ow the static and dynamic characteristics of measurement s | ystems. | | | |
| ٠ | To stu | udy about the various types of sensors viz. Resistive, Reactive | ve. | | | |
| • | To stu | udy about Self- generating sensors. | | | | |
| • | To kr | now the different types digital and semiconductor sensors. | | | | |
| • | To stu | ady different types of actuators and their usage. | | | | |
| UNIT I | | INTRODUCTION TO MEASUREMENT SYST | TEMS | | | 9 |
| character measuren | istics: 1 nent sys | tatic characteristics of measurement systems, accuracy, pre- inearity, resolution, systematic errors, random errors, dy stems: zero-order, first-order, and second-order measuremen | namic | charact | eristi | cs of nse. |
| UNIT I | I | RESISTIVE AND REACTIVE SENSORS | | | | 9 |
| dependen | t resist | : potentiometers, strain gages, resistive temperature detectors ors, Signal conditioning for resistive sensors: Wheatston | e bridg | ge, sen | sor b | light oridge |
| dependen calibration reduction sensors, 1 | t resist n and , Reacta inear va | | e bridg ference ors, diffe | ge, sen and i erential | sor b nterfe , indu | light oridge rence active |
| dependen calibration reduction sensors, 1 | t resist n and , Reacta inear va nditioni | ors, Signal conditioning for resistive sensors: Wheatston compensation, Instrumentation amplifiers, sources of inter- ance variation and electromagnetic sensors, capacitive sensor ariable differential transformers (LVDT), magneto elastic sen- | e bridg ference ors, diffe | ge, sen and i erential | sor b nterfe , indu | light- pridge rence active nsors |
| dependen calibration reduction sensors, 1 Signal con UNIT I Self-gene photovolt chopper | t resist n and o , Reacta inear va nditioni II erating taic ser and lo | ors, Signal conditioning for resistive sensors: Wheatston compensation, Instrumentation amplifiers, sources of inter- ance variation and electromagnetic sensors, capacitive sensor ariable differential transformers (LVDT), magneto elastic sen ng for reactance-based sensors & application to the LVDT. | e bridg ference ors, diffe nsors, h | ge, sen and i erential all effe electric neratin | sor b nterfe , indu ect ser c ser g ser | light- oridge rence active nsors 9 nsors |
| dependen calibration reduction sensors, 1 Signal con UNIT I Self-gene photovolt chopper | t resist n and , Reacta inear va nditioni II trating taic ser and lo s, noise V | ors, Signal conditioning for resistive sensors: Wheatston compensation, Instrumentation amplifiers, sources of inter- ance variation and electromagnetic sensors, capacitive sensor ariable differential transformers (LVDT), magneto elastic sen ng for reactance-based sensors & application to the LVDT. SELF-GENERATING SENSORS sensors: thermoelectric sensors, piezoelectric sensors nsors, electrochemical sensors, Signal conditioning for w-drift amplifiers, offset and drifts amplifiers, electron | e bridg ference ors, diffe nsors, h | ge, sen and i erential all effe electric neratin | sor b nterfe , indu ect ser c ser g ser | light- pridge rence active nsors sors harge |
| dependen calibration reduction sensors, 1 Signal con UNIT I Self-gene photovolt chopper amplifiers UNIT I Relays, S control, | t resist n and , Reacta inear va nditioni II trating taic ser and lo s, noise V Solenoid 4-to-20 | ors, Signal conditioning for resistive sensors: Wheatston compensation, Instrumentation amplifiers, sources of inter- ance variation and electromagnetic sensors, capacitive sensor ariable differential transformers (LVDT), magneto elastic sen- ng for reactance-based sensors & application to the LVDT. SELF-GENERATING SENSORS sensors: thermoelectric sensors, piezoelectric sensors nsors, electrochemical sensors, Signal conditioning for w-drift amplifiers, offset and drifts amplifiers, electron in amplifiers. ACTUATOR CHARACTERISTICS AND | e bridg ference ors, diffe nsors, h , pyro self-gen neter at | ge, sen and i erential all effe electric neratin mplifie | sor b nterfe , indu ect ser g ser rs, c and r | light- pridge rence active nsors 9 nsors harge 9 notor |
| dependen calibration reduction sensors, 1 Signal con UNIT I Self-gene photovolt chopper amplifiers UNIT I Relays, S control, | t resist n and a , Reacta inear vanditioni II trating taic ser and lo s, noise V Solenoid 4-to-20 7 | ors, Signal conditioning for resistive sensors: Wheatston compensation, Instrumentation amplifiers, sources of inter- ance variation and electromagnetic sensors, capacitive sensor ariable differential transformers (LVDT), magneto elastic sen- ing for reactance-based sensors & application to the LVDT. SELF-GENERATING SENSORS sensors: thermoelectric sensors, piezoelectric sensors nsors, electrochemical sensors, Signal conditioning for w-drift amplifiers, offset and drifts amplifiers, electron in amplifiers. ACTUATOR CHARACTERISTICS AND APPLICATIONS drive, Stepper Motors, Voice-Coil actuators, Servo Motor mA Drive, Hydraulic actuators, variable transformer | e bridg ference ors, diffe nsors, h , pyro self-gen neter an rs, DC r rs: syn | ge, sen and i erential all effe electric neratin mplifie notors chros, | sor b nterfe , indu ect ser g ser rs, c and r | light- pridge rence active nsors sors harge |
| dependen calibration reduction sensors, 1 Signal con UNIT I Self-gene photovolt chopper amplifiers UNIT I Relays, S control, Inductosy UNIT V Digital se wire strai | t resist n and a , Reacta inear va nditioni II trating taic ser and lo s, noise V Solenoid 4-to-20 7 censors: j in gage | ors, Signal conditioning for resistive sensors: Wheatston compensation, Instrumentation amplifiers, sources of inter ance variation and electromagnetic sensors, capacitive sensor ariable differential transformers (LVDT), magneto elastic set ing for reactance-based sensors & application to the LVDT. SELF-GENERATING SENSORS sensors: thermoelectric sensors, piezoelectric sensors asors, electrochemical sensors, Signal conditioning for w-drift amplifiers, offset and drifts amplifiers, electron in amplifiers. ACTUATOR CHARACTERISTICS AND APPLICATIONS I drive, Stepper Motors, Voice-Coil actuators, Servo Motor mA Drive, Hydraulic actuators, variable transformer wer-to-digital and digital-to-resolver converters. DIGITAL SENSORS AND SEMICONDUCTOF | e bridg ference ors, diffe nsors, h , pyro self-gen neter at rs, DC r rs: syn R DEV al therm | ge, sen and i erential all effe electric neratin mplifie notors chros, TCE | sor b nterfe , indu ect ser g ser g ser rrs, c and r reso | light pridge rence active nsors nsors harge noto lvers |

magneto diodes and magneto transistors, photodiodes and phototransistors, sensors based on MOSFET transistors, CCD imaging sensors, ultrasonic sensors, fiber-optic sensors.

TOTAL: 45 PERIODS

| OUTC | OMES: |
|-------|--|
| • | Discuss measurement systems. |
| • | Knowledge about resistive and reactive sensors. |
| • | Discuss Self-generating sensors. |
| • | Analyze the characteristics of Actuators. |
| • | Evaluate digital sensors and semiconductor device sensors. |
| REFEI | RENCES: |
| 1. | A.M. Pawlak," Sensors and Actuators in Mechatronics Design and Applications", CRC Press, 2006. |
| 2. | D. Johnson, "Process Control Instrumentation Technology", John Wiley and Sons, Eighth Edition, 2006. |
| 3. | D.Patranabis, "Sensors and Transducers", TMH, Second Edition, 2003. |
| 4. | E.O. Doeblin, "Measurement System : Applications and Design", McGraw Hill publications, Fifth Edition, 2007. |
| 5. | G.Brooker, Introduction to Sensors for ranging and imaging, Yesdee, 2009. |
| 6. | H.K.P. Neubrat, "Instrument Transducers – An Introduction to Their Performance and Design", Oxford University Press, Second Edition. |
| 7. | I.Sinclair, "Sensors and Transducers", Elsevier, 3rd Edition, 2011. |
| 8. | J.Wilson, "Sensor Technology Handbook", Elsevier, First Edition, 2004. |
| 9. | K. James, PC Interfacing and Data acquisition, Elsevier, First Edition. |
| 10. | Ramon Pallás-Areny, John G. Webster, "Sensors and Signal Conditioning", 2nd edition, John Wiley and Sons, 2012. |
| 11. | C.W. de Silva, "Sensors and Actuators: Control System Instrumentation", CRC Press, Second Edition, 2015. |

| 17AEPE08 | | | MEMS AND NEMS | L | T | Р | С |
|---|---|---|--|--|---|--|--|
| | | | | 3 | 0 | 0 | 3 |
| OBJEC | TIVE | ES: | | | | _11 | |
| ٠ | To ir | ntrodu | ce the concepts of micro electromechanical devices. | | | | |
| ٠ | To k | now t | he fabrication process of Microsystems. | | | | |
| ٠ | To k | now t | he design concepts of micro sensors and micro actuate | ors. | | | |
| ٠ | To fa | amilia | rize concepts of quantum mechanics and nano system | s. | | | |
| • | To ir | ntrodu | ce various opportunities in the emerging field of MEN | AS. | | _ | |
| UNIT I | | OV | ERVIEW | | | | 9 |
| NEMS, N | IEMS a | and N | ring and Science: Micro and Nanoscale systems, Introduct EMS – Applications, Devices and structures. Materials metals. | | U | | |
| compound | , p == j | | | | | | |
| UNIT I Microsys film depo etching, 6 | I fail fail fail fail fail fail fail fail | bricat s: LPC | MS FABRICATION TECHNOLOGIES ion processes: Photolithography, Ion Implantation, D CVD, Sputtering, Evaporation, Electroplating; Etching cal etching; Micromachining: Bulk Micromachining, (LIGA and LIGA-like) Technology; Packaging; | g techniq Surface | ues: D Micro | ry and machi | Thin d wet ning |
| UNIT I Microsys film depo etching, e High As | I tem fab ositions electroo pect- 1 packag | bricat s: LPC chemi Ratio ging t | ion processes: Photolithography, Ion Implantation, E | g techniq Surface | ues: D Micro | ry and machi | Thin d wet ning, ging, |
| UNIT I Microsys film depo etching, e High As Essential UNIT I MEMS Se | I tem fabositions electrod pect- packag II ensors: sistive | bricat s: LPC chemi Ratio ging t MI Desiş Pressu | ion processes: Photolithography, Ion Implantation, E CVD, Sputtering, Evaporation, Electroplating; Etching cal etching; Micromachining: Bulk Micromachining, (LIGA and LIGA-like) Technology; Packaging: echnologies, Selection of packaging materials. CRO SENSORS on of Acoustic wave sensors, resonant sensor, Vibratory re sensors- engineering mechanics behind these Micros | g techniq Surface Microsys gyrosco | ues: D Micron stems pe, Cap | ry and machi packa | Thin d wet ning, ging, g g g e and |
| UNIT I Microsys film depo etching, e High As Essential UNIT I MEMS So Piezo Res | I tem fai positions electroc pect- 1 packag II ensors: sistive 1 ressure | bricat s: LPC chemi Ratio ging t MI Desig Pressu senso | ion processes: Photolithography, Ion Implantation, E CVD, Sputtering, Evaporation, Electroplating; Etching cal etching; Micromachining: Bulk Micromachining, (LIGA and LIGA-like) Technology; Packaging: echnologies, Selection of packaging materials. CRO SENSORS on of Acoustic wave sensors, resonant sensor, Vibratory re sensors- engineering mechanics behind these Micros | g techniq Surface Microsys gyrosco | ues: D Micron stems pe, Cap | ry and machi packa | Thin d wet ning ging ging g e and Piezo |
| UNIT I Microsys film depo etching, e High As Essential UNIT I MEMS So Piezo Res resistive p UNIT I Design of piezoelect Micromec | I tem fa positions electroc pect- packag II ensors: sistive ressure V Actuat ric crys hanical | bricat s: LPC chemi Ratio ging t MIC Desig Pressu senso MIC ors: A stals, A Moto | ion processes: Photolithography, Ion Implantation, E CVD, Sputtering, Evaporation, Electroplating; Etching cal etching; Micromachining: Bulk Micromachining, (LIGA and LIGA-like) Technology; Packaging: echnologies, Selection of packaging materials. CRO SENSORS m of Acoustic wave sensors, resonant sensor, Vibratory re sensors- engineering mechanics behind these Micros r. | g techniq Surface Microsys gyrosco sensors. (ory Alloy bar, Con | ues: D Micros stems pe, Cap Case st ys, Actu nb drive | ry and machi packa acitiv udy: 1 hation e actua | Thin d wet ning, ging, ging, g e and Piezo- 9 using ators), |
| UNIT I Microsys film depo etching, e High As Essential UNIT I MEMS So Piezo Res resistive p UNIT I Design of piezoelect Micromec | I tem fa positions electrod pect- packag II ensors: sistive ressure V Actuat ric crys chanical pol inter | bricat s: LPC chemi Ratio ging t MIC Desig Pressu senso MIC ors: A stals, A Moto rferen | ion processes: Photolithography, Ion Implantation, E CVD, Sputtering, Evaporation, Electroplating; Etching cal etching; Micromachining: Bulk Micromachining, (LIGA and LIGA-like) Technology; Packaging: echnologies, Selection of packaging materials. CRO SENSORS of Acoustic wave sensors, resonant sensor, Vibratory re sensors- engineering mechanics behind these Micros r. CRO ACTUATORS ctuation using thermal forces, Actuation using shape mem- actuation using Electrostatic forces (Parallel plate, Torsion rs and pumps. Case study: Comb drive actuators. compon | g techniq Surface Microsys gyrosco gensors. (hory Alloy bar, Con ents , Ey | ues: D Micros stems pe, Cap Case st ys, Actu nb drive | ry and machi packa acitiv udy: 1 hation e actua | Thin d wet ning ging 9 e and Piezo 9 using ators) itter |
| UNIT I Microsys film depo etching, o High As Essential UNIT I MEMS So Piezo Res resistive p UNIT I Design of piezoelect Micromec inter-symb UNIT V Atomic S Equation | I tem fai positions electrod pect- packag II ensors: sistive v Actuate ric crys chanical pol inter / Structur and V | bricat s: LPC chemi Ratio ging t MIC Desig Pressu senso MIC ors: A stals, A stals, A moto rferen NA | ion processes: Photolithography, Ion Implantation, E CVD, Sputtering, Evaporation, Electroplating; Etching cal etching; Micromachining: Bulk Micromachining, (LIGA and LIGA-like) Technology; Packaging: echnologies, Selection of packaging materials. CRO SENSORS on of Acoustic wave sensors, resonant sensor, Vibratory re sensors- engineering mechanics behind these Micros r. CRO ACTUATORS ctuation using thermal forces, Actuation using shape mem- actuation using Electrostatic forces (Parallel plate, Torsion rs and pumps. Case study: Comb drive actuators. compon be Bit-error rate ,Timing analysis. | g techniq Surface Microsys gyrosco gyrosco sensors. (hory Alloy bar, Con ents , Ey NICS e Dynar structure | pe, Cap Case st ys, Actu nb drive e diagra | ry and machi packa pacitiv udy: I nation e actua ums , j chrod Mole | d wet ning, ging, ging, 9 e and Piezo- 9 using ators), itter , 9 inger ccular |

| OUTC | OMES: |
|-------|---|
| • | Be familiar with the important concepts related to MEMS. |
| • | Outline MEMS fabrication technology. |
| • | Design of micro actuators. |
| • | Analyze the engineering mechanism of micro sensors. |
| • | Outline nano systems and Quantum mechanics. |
| REFEI | RENCES: |
| 1. | C.Liu, "Foundations of MEMS", Pearson education India limited, Second Edition, 2011. |
| 2. | M.Madou, "Fundamentals of Microfabrication and NanoTechnology", CRC press, Third Edition, 2011. |
| 3. | S.D. Senturia," Micro system Design", Kluwer Academic Publishers,2001 |
| 4. | S.E.Lyshevski, "MEMS and NEMS: Systems, Devices, and Structures" CRC Press, 2002. |
| 5. | T.R.Hsu ,"MEMS and Microsystems Design and Manufacture", Tata McGraw Hill, First Edition, 2002 |

SEMESTER- II

ELECTIVE III

| 17AEPE09 | | DSP PROCESSOR ARCHITECTURE AND PROGRAMMING | L | Т | Р | С |
|--|---|---|---|---|------------------------------------|---|
| | | | 3 | 0 | 0 | 3 |
| OBJEC | TIVES | S: | | | 1 1 | |
| • | U | ve an exposure to the various DSP architectures and to develop processors. | op app | lication | ıs usir | ng |
| ٠ | Knowl | ledge on digital signal processor basics. | | | | |
| ٠ | Knowl | ledge on third generation DSP Architecture. | | | | |
| • | Knowl | ledge on programming skills. | | | | |
| • | Knowl | ledge on advanced DSP architectures and some applications. | | | | |
| UNIT I | I | FUNDAMENTALS OF PROGRAMMABLE DS | Ps | | | 9 |
| - | | Iultiplier accumulator – Modified Bus Structures and Mem | - | | | |
| - | | nemory – Multi-port memory – VLIW architecture- Pipelinir – On chip Peripherals. | ng – Sj | pecial A | Addre | ssing |
| - | P-DSPs | | 1g – Sj | | Addre | ssing 9 |
| modes in UNIT II Architectu Pipeline | P-DSPs [Sure – Asstructure | – On chip Peripherals. | langua | age Ins | tructi | 9 ons - |
| modes in UNIT II Architectu Pipeline | P-DSPs [S Ire – As structure g real tir | s – On chip Peripherals. SPECIAL FUNCTIONS ssembly language syntax - Addressing modes – Assembly e, Operation – Block Diagram of DSP starter kit – Ap | langua | age Ins | tructi | 9 ons - |
| modes in a UNIT II Architectu Pipeline s processing UNIT II Architectu Starter Ki | P-DSPsI S Ire - Asstructureg real tirIIIIIre of tht Suppo | s – On chip Peripherals. SPECIAL FUNCTIONS ssembly language syntax - Addressing modes – Assembly e, Operation – Block Diagram of DSP starter kit – Ap me signals. | langua plicati em: In | age Ins on Pro | tructi ogram | 9 ons - s for 9 DSP |
| modes in a UNIT II Architectu Pipeline s processing UNIT II Architectu Starter Ki | P-DSPs I S Ire – As structure g real tir I I Ire of th t Suppo Fools – A | SPECIAL FUNCTIONS ssembly language syntax - Addressing modes – Assembly e, Operation – Block Diagram of DSP starter kit – Appme signals. LINEAR PROGRAMMING me C6x Processor - Instruction Set - DSP Development System ort Tools- Code Composer Studio - Support Files - Program | langua plicati em: In | age Ins on Pro | tructi ogram | 9 ons - s for 9 DSP |
| modes in a UNIT II Architectu Pipeline s processing UNIT II Architectu Starter Ki the DSK 7 UNIT IV Architectu | P-DSPs I S Ire – As structure g real tir I I Ire of th t Suppo Fools – A V I Ire of A | SPECIAL FUNCTIONS ssembly language syntax - Addressing modes – Assembly e, Operation – Block Diagram of DSP starter kit – Ap me signals. LINEAR PROGRAMMING me C6x Processor - Instruction Set - DSP Development Systemet Tools- Code Composer Studio - Support Files - Program Application Programs for processing real time signals. | langua plicati em: In ming Addre | age Ins on Pro troduct Examp | tructi ogram ion – les to | 9 ons - s for 9 DSP Test 9 |
| modes in a UNIT II Architectu Pipeline s processing UNIT II Architectu Starter Ki the DSK 7 UNIT IV Architectu | P-DSPs I S Ire – As structure g real tir I I Ire of th t Suppo Fools – A V I Ire of A languag | SPECIAL FUNCTIONS ssembly language syntax - Addressing modes – Assembly e, Operation – Block Diagram of DSP starter kit – Appme signals. LINEAR PROGRAMMING the C6x Processor - Instruction Set - DSP Development System for trools- Code Composer Studio - Support Files - Program Application Programs for processing real time signals. LINEAR PROGRAMMING ADSP-21XX and ADSP-210XX series of DSP processors- | langua plicati em: In ming Addre | age Ins on Pro troduct Examp | tructi ogram ion – les to | 9 ons - s for 9 DSP Test 9 |
| modes in a UNIT II Architectu Pipeline s processing UNIT II Architectu Starter Ki the DSK 7 UNIT IV Architectu assembly UNIT V Architectu | P-DSPs I = As structure g real tir I = I ure of th t Suppo Fools - A V = I ure of A languag A ure of A languag A C G X - A | SPECIAL FUNCTIONS ssembly language syntax - Addressing modes – Assembly e, Operation – Block Diagram of DSP starter kit – Appme signals. LINEAR PROGRAMMING ne C6x Processor - Instruction Set - DSP Development Systemet Tools- Code Composer Studio - Support Files - Program Application Programs for processing real time signals. LINEAR PROGRAMMING ADSP-21XX and ADSP-210XX series of DSP processors-ge instructions – Application programs –Filter design, FFT care | langua plicati em: In ming Addre alculat | age Ins on Pro troduct Examp essing 1 ion. | tructiogram | 9 ons - s for 9 DSP Test 9 s and 9 re of |

| OUTC | OMES: |
|------|--|
| • | Learn the architecture details and instruction sets of DSP. |
| • | Understand the special functions of DSP architecture and programming. |
| • | Interfacing of programmable DSP devices for system implementation. |
| • | Create application programs. |
| • | Evaluate features of DSP family processors. |
| REFE | RENCES: |
| 1. | A.Singh and S. Srinivasan, "Digital Signal Processing – Implementations using DSP Microprocessors with Examples from TMS320C54xx", Cengage Learning India Private Limited Delhi, 2012. |
| 2. | B.Venkataramani and M.Bhaskar, "Digital Signal Processors – Architecture, Programming and Applications" – Tata McGraw – Hill Publishing Company Limited. New Delhi, Second Edition, 2010. |
| 3. | RulphChassaing, D.S.Reay, "Digital Signal Processing and Applications with the TMS320C6713 and TMS320C6416 DSK", A JOHN WILEY & SONS, INC., PUBLICATION, Second Edition, 2011. |
| 4. | User guides Texas Instrumentation, Analog Devices, Motorola. |

| 17AEPE10 | | | | RF | SYS' | ГЕМ | 1 DE | SIGN | | | L | Τ | P | С |
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| | | | | | | | | | | | 3 | 0 | 0 | 3 |
| OBJEC | CTIVE | S: | | | | | | | | • | | | | |
| • | | troduce rtant blo | | | | | n and | design p | orinciples | associ | ated | with th | e | |
| ٠ | To de | esign RI | F ampli | fier. | | | | | | | | | | |
| ٠ | To st | udy abo | out the o | charact | eristics | ofos | scillat | ors, mix | ers. | | | | | |
| • | | | | | | | | the appr with the | opriate di RFEs. | gital c | comm | unicati | ion re | elated |
| ٠ | To st | udy abo | out the o | charact | eristics | of P | LL ar | d freque | ncy synth | esizer | s. | | - | |
| UNIT I | [| | S PHY ARCH | | , | | SCEI | VER S | PECIF | [CAT | TON | NS | | 9 |
| theory, over a c | Noise I commur | Figure, | THD, I link, | IP2, IP Homo | P3, Sens dyne R | sitivi Receiv | ty, SI ver, H | FDR, Ph Heterody | ker, popc ase noise ne Recei tep upcon | - Spe ver, I | ecifica mage | ation d reject | istrib , Lo | outior |
| UNIT I | Ι | IMPE | EDAN | CE M | [ATC] | HIN | G A | ND AN | IPLIFII | ERS | | | | 9 |
| Gate, Co | ommon quency | Source amplif | Ampli ier des | fiers, C ign, Po | DC Tim ower m | ne co natch | nstan and | ts in bar Noise n | edance ma dwidth ea hatch, Sir As. | stimati | ion a | nd enh | ance | ment |
| UNIT I | II | FEED | DBAC | K SY | STEM | IS A | IS AND POWER AMPLIFIERS | | | | | | 9 | |
| domain c | consider mplifier | ations, | Compe | ensation | n, Gene | eral n | nodel | – Class | ocus techr A, AB, F g technic | 3, C, I | , Е | and F a | ampli | ifiers |
| UNIT I | V | MIXE | ERS A | ND C | SCIL | LLA | TOR | S | | | | | | 9 |
| balanced | and do | uble bal | lanced | mixers | , subsar | mplin | ng miz | kers, Osc | rs, Multip illators de scillators, | escribi | ng Fi | unction | - | |
| UNIT V | V | PLL A | AND I | FREQ | QUEN | CY | SYN | THES | ZERS | | | | | 9 |
| Linearise frequenc | | | | | | | | - | s and Cha | arge pi | umps | , Intege | er-N | |
| 1 | | | | | | | | | | | | | | |

| OUTC | OUTCOMES: | | |
|-------|--|--|--|
| • | Understand the specifications and architecture design of transceivers. | | |
| • | Knowledge of impedance matching networks and design of high frequency amplifiers. | | |
| • | Design of feedback systems and power amplifiers. | | |
| • | Knowledge of mixers and oscillators. | | |
| • | Design of PLL and Frequency synthesizers. | | |
| REFEI | RENCES: | | |
| 1. | B.Razavi, "Design of Analog CMOS Integrated Circuits", McGraw Hill, Second Edition, 2017. | | |
| 2. | B.Razavi, "RF Microelectronics", Pearson Education, Second Edition, 2012. | | |
| 3. | J.Crols, M.Steyaert, "CMOS Wireless Transceiver Design", Kluwer Academic Publishers, 1997. | | |
| 4. | Recorded lectures and notes available at . http://www.ee.iitm.ac.in/~ani/ee6240/ | | |
| 5. | T.Lee, "The Design of CMOS Radio Frequency Integrated Circuits", Cambridge University Press, Second Edition, 2004. | | |

| | | | 3 | 0 | 0 | 3 |
|--|---|---|-----------------------------|--------------------------|----------------|---------------------------|
| OBJEC | ΓΙν | ES: | | | | |
| • | To study basic concepts of processing speech signals. | | | | | |
| • | To s | tudy and analyse various M-band filter-banks for audio coding | g. | | | |
| • | To u | nderstand audio coding based on transform coders. | | | | |
| • | To s | tudy time and frequency domain speech processing methods | | | | |
| • | To u | nderstand predictive analysis of speech. | | | | |
| UNIT I | | MECHANICS OF SPEECH AND AUDIO | | | | 9 |
| of Hearin Masking- versus obj | g - (Non-s jectiv | emes – Phonetic and Phonemic alphabets – Articulatory featu Critical Bands- Simultaneous Masking, Masking-Asymmet simultaneous Masking - Perceptual Entropy - Basic measuring e perceptual testing - The perceptual audio quality measuring audio quality. | ry, and philos e (PAC | d the ophy - QM) - | Sprea Subje | nd of ective nitive |
| UNIT II | | TIME-FREQUENCY ANALYSIS: FILTER BAI TRANSFORMS | NKS A | AND | | 9 |
| Coding: I Structured Cosine M Transform | Introduction - Analysis-Synthesis Framework for M-band Filter Banks- Filter Banks for Aud Coding: Design Considerations - Quadrature Mirror and Conjugate Quadrature Filters - Tree Structured QMF and CQF M-band Banks - Cosine Modulated "Pseudo QMF" M-band Banks Cosine Modulated Perfect Reconstruction (PR) M-band Banks and the Modified Discrete Cosi Transform (MDCT) - Discrete Fourier and Discrete Cosine Transform - Pre-echo Distortion- Pre- echo Control Strategies. | | | | | Tree- nks - osine |
| UNIT II | Ι | AUDIO CODING AND TRANSFORM CODERS | 5 | | | 9 |
| Coding - Q Johnston H Audio Co | Lossless Audio Coding – Lossy Audio Coding - ISO-MPEG-1A, 2A, 2A-Advaned, 4A Audio Coding - Optimum Coding in the Frequency Domain - Perceptual Transform Coder –Brandenburg - Johnston Hybrid Coder - CNET Coders - Adaptive Spectral Entropy Coding –Differential Perceptual Audio Coder - DFT Noise Substitution -DCT with Vector Quantization -MDCT with Vector Quantization. | | | | | |
| UNIT IV | 7 | TIME AND FREQUENCY DOMAIN METHOD SPEECH PROCESSING | S FO | R | | 9 |
| Magnitude analysis - | e – Ze - For phic | arameters of Speech signal – Methods for extracting the parameters of Speech signal – Methods for extracting the parameter crossing Rate – Silence Discrimination using ZCR and end mant extraction – Pitch Extraction using time and freque Speech Analysis: Cepstral analysis of Speech – Formant Vocoders. | ergy Sh | ort Tiı domair | ne Fo n me | ourier thods |
| | | 62 | | | | |

SPEECH SIGNAL PROCESSING

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| UNIT V | V | PREDICTIVE ANALYSIS OF SH | PEECH | 9 | |
|-----------------------|--|--|--------------------------------------|-----|--|
| method – algorithm | Formulation of Linear Prediction problem in Time Domain – Basic Principle – Auto correlati method – Covariance method – Solution of LPC equations – Cholesky method – Durbin''s Recursi algorithm – lattice formation and solutions – Comparison of different methods – Application of LI parameters – Pitch detection using LPC parameters – Formant analysis – VELP – CELP. | | | | |
| | | | TOTAL: 45 PERIODS | | |
| OUTCO | OME | S: | | | |
| • | Abili | ty to understand the mechanism of speech s | signal processing. | | |
| • | Analy | ysis of filter banks and transforms in time d | omain. | | |
| • | Evalu | ate audio coding and transform coders. | | | |
| • | Discu | ass time and frequency domain methods for | speech processing. | | |
| • | • Ability to analyze predictive analysis of speech. | | | | |
| REFER | REFERENCES: | | | | |
| 1. | 1. B.Gold and N.Morgan, "Speech and Audio Signal Processing", Wiley and Sons, Second Edition, 2011. | | Second | | |
| 2. | L.R.Rabiner and R.W.Schaffer, "Digital Processing of Speech Signals", Prentice Hall, 1979. | | | | |
| 3. | <i>3. M.Kahrs, K.Brandenburg, "Applications of Digital Signal Processing to Audio And Acoustics", Kluwer Academic Publishers, 1998.</i> | | | | |
| 4. | U.Zöl | zer, "Digital Audio Signal Processing", John W | Viley& sons Ltd , Second Edition, 20 | 08. | |

| 17AEPE12 | | SOLID STATE DEVICE MODELLING AND SIMULATION | L | Т | Р | С |
|---|--|--|--|---|--------|--|
| | | | 3 | 0 | 0 | 3 |
| OBJEC | CTIVE | S: | · | | | |
| ٠ | To stu | udy physics of MOSFET devices. | | | | |
| ٠ | To un | derstand the concept of device modelling. | | | | |
| ٠ | To lea | arn multistep method. | | | | |
| ٠ | To stu | dy mathematical techniques of device simulations. | | | | |
| • | To stu | dy device simulations. | | | | |
| UNIT I | [] | MOSFET DEVICE PHYSICS MOSFET | | | | 9 |
| transistor transistor | rs, Equiv | operation, Basic modeling, Advanced MOSFET modeling valent circuit representation of MOS transistor, High frequ .C small signal modeling, model parameter extraction, in itors, Inductors. | uency t | ehavio | r of | MOS |
| UNIT II DEVICE MODELLING | | | | | | |
| UNITI | | DEVICE MODELLING | | | | 9 |
| Prime im analysis | portance equatior | e of circuit and device simulations in VLSI; Nodal, mesh, m ns. Solution of network equations: Sparse matrix technique n Newton-Raphson technique, convergence and stability. | | | | ybrid |
| Prime im analysis | aportance equatior through | e of circuit and device simulations in VLSI; Nodal, mesh, m as. Solution of network equations: Sparse matrix technique | | | | • |
| Prime im analysis networks UNIT I Solution | aportance equation s through (II) of stiff | e of circuit and device simulations in VLSI; Nodal, mesh, m ns. Solution of network equations: Sparse matrix technique n Newton-Raphson technique, convergence and stability. | es, solu | tion of | non | ybrid linear 9 |
| Prime im analysis networks UNIT I Solution | nportance equation s through (II) of stiff s, genera (V) | e of circuit and device simulations in VLSI; Nodal, mesh, m ns. Solution of network equations: Sparse matrix technique in Newton-Raphson technique, convergence and stability. MULTISTEP METHODS systems of equations, adaptation of multistep methods to the | es, solu | tion of | non | ybrid linear 9 etrical |
| Prime im analysis networks UNIT I Solution networks UNIT I Poisson o | aportance equation s through of stiff s, genera V equation s, trap | e of circuit and device simulations in VLSI; Nodal, mesh, m ns. Solution of network equations: Sparse matrix technique in Newton-Raphson technique, convergence and stability. MULTISTEP METHODS systems of equations, adaptation of multistep methods to a l purpose circuit simulators. MATHEMATICAL TECHNIQUES DEVICE | es, solu the solu equation | ation of | f elec | ybrid linear 9 etrical 9 |
| Prime im analysis networks UNIT I Solution networks UNIT I Poisson e equations | aportance equation s through (II) of stiff s, genera (V) equation s, trap on. | e of circuit and device simulations in VLSI; Nodal, mesh, m as. Solution of network equations: Sparse matrix technique in Newton-Raphson technique, convergence and stability. MULTISTEP METHODS systems of equations, adaptation of multistep methods to a l purpose circuit simulators. MATHEMATICAL TECHNIQUES DEVICE SIMULATIONS , continuity equation, drift-diffusion equation, Schrodinger | es, solu the solu equation | ation of | f elec | ybrid linear 9 etrical 9 |
| Prime im analysis networks UNIT I Solution networks UNIT I Poisson of equations generation | aportance equation s through of stiff s, genera (V equation s, trap on. V | e of circuit and device simulations in VLSI; Nodal, mesh, m ns. Solution of network equations: Sparse matrix technique in Newton-Raphson technique, convergence and stability. MULTISTEP METHODS systems of equations, adaptation of multistep methods to a l purpose circuit simulators. MATHEMATICAL TECHNIQUES DEVICE SIMULATIONS , continuity equation, drift-diffusion equation, Schrodinger rate, finite difference solutions to these equations in 1 SIMULATION OF DEVICES characteristics of simple devices like p-n junction, MOS of | es, solu the solu equatic D and | ation of ution of on, hydr 2D sj | f elec | ybrid linear 9 etrical 9 namic grid 9 |

| OUTC | OUTCOMES: | | | |
|------|--|--|--|--|
| • | Able to understand the importance of MOS Capacitor and Small signal modelling. | | | |
| • | Apply and determine the drift diffusion equation and stiff system equation. | | | |
| • | Analyze circuits using parasitic BJT parameters and Newton Raphson method. | | | |
| • | Modelling of MOS transistor using Schrodinger equation and Multistep methods. | | | |
| • | Ability to do simulation to compute the characteristics of MOSFET devices. | | | |
| REFE | RENCES: | | | |
| 1. | Arora, N., "MOSFET Modelling for VLSI Simulation", Cadence Design Systems, 2007. | | | |
| 2. | Chua, L.O. and Lin, P.M., "Computer-Aided Analysis of Electronic Circuits: Algorithms and Computational Techniques", Prentice-Hall., 1975. | | | |
| 3. | <i>Fjeldly, T., Yetterdal, T. and Shur, M., "Introduction to Device Modelling and Circuit Simulation", Wiley-Interscience., 1997.</i> | | | |
| 4. | Grasser, T., "Advanced Device Modelling and Simulation", World Scientific Publishing Company., 2003. | | | |
| 5. | Selberherr, S., "Analysis and Simulation of Semiconductor Devices", Springer- Verlag., 1984. | | | |
| 6. | T.Ytterdal, Y.Cheng and Tor A. FjeldlyWayne Wolf, "Device Modelling for Analog and RF CMOS Circuit Design", John Wiley & Sons Ltd, 2003. | | | |

SEMESTER- III

ELECTIVE IV

17AEPE13

ADVANCED MICROPROCESSOR AND MICROCONTROLLER ARCHITECTURES

| L | Т | Р | С |
|---|---|---|---|
| 3 | 0 | 0 | 3 |

OBJECTIVES:

| • | To familiarize about the features, specification and features of modern microprocessors. |
|---|--|
| • | To gain knowledge about the architecture of Intel 32 and 64 bit microprocessors and salient features associated with them. |
| • | To familiarize about the features, specification and features of modern microcontrollers. |
| • | To gain knowledge about the 32 bit microcontrollers based on ARM and PIC32 architectures. |
| • | To study interfacing of microprocessor/microcontroller with the external peripheral. |

UNIT I

FEATURES OF MODERN MICROPROCESSORS

9

Evolution of microprocessors - Data and Address buses - clock speed - memory interface - multicore architectures - cache memory hierarchy - operating modes - super scaler execution - dynamic execution - over clocking - integrated graphics processing - performance benchmarks.

UNIT II HIGH PERFORMANCE CISC ARCHITECTURES

9

9

Introduction to IA 32 bit architecture – Intel Pentium Processors family tree – Memory Management – Branch prediction logic - Superscalar architecture – Hyper threading technology – 64 bit extension technology – Intel 64 bit architecture - Intel Core processor family tree – Turbo boost technology – Smart cache - features of Nehalem microarchitecture

UNIT III HIGH PERFORMANCE RISC ARCHITECTURE – ARM

RISC architecture merits and demerits – The programmer's model of ARM Architecture – 3- stage pipeline ARM organization - ARM instruction execution – Salient features of ARM instruction set - ARM architecture profiles (A, R and M profiles)

UNIT IV FEATURES OF MODERN MICROCONTROLLER

9

Introduction to microcontrollers – microcontroller vs microprocessors – microcontroller architecture - Processor Core – Memory interfaces– Communication interfaces (SPI,I2C, USB and CAN) – ADC - PWM – Watchdog timers – Interrupts – Debugging interfaces .

UNIT V HIGH PERFORMANCE MICROCONTROLLER ARCHITECTURES

Introduction to the Cortex-M Processor Family - ARM 'Cortex-M3' architecture for microcontrollers – Thumb 2 instruction technology – Internal Registers - Nested Vectored Interrupt controller -Memory map - Interrupts and exception handling – Applications of Cotex-M3 architecture

TOTAL : 45 PERIODS

| OUTCO | OUTCOMES: | | | | |
|-------|---|--|--|--|--|
| • | To explain the features and important specifications of modern microprocessors. | | | | |
| • | To explain the salient features CISC microprocessors based on IA-32 bit and IA-64 bit architectures. | | | | |
| • | To explain the salient features RISC processors based on ARM architecture and different application profiles of ARM core. | | | | |
| • | To explain the features and important specifications of modern microcontrollers. | | | | |
| • | To explain about ARM – M3 architecture and its salient features. | | | | |
| REFER | ENCES: | | | | |
| 1. | Barry. B. Breg," The Intel Microprocessors", PHI,2008. | | | | |
| 2. | Gene .H.Miller ." Micro Computer Engineering," Pearson Education, 2003. | | | | |
| 3. | Intel Inc, "Intel 64 and IA-32 Architectures Developer"s Manual", Volume-I, 2016 | | | | |
| 4. | J. Yiu, "The Definitive Guide to the ARM ® Cortex-M3", Newnes, 2010. | | | | |
| 5. | S.Mueller, "Upgrading and Repairing PCs", 20th edition, Que. | | | | |
| 6. | S.Furber, "" ARM System –On –Chip architecture "Addision Wesley , 2000. | | | | |
| 7. | T. Martin, "The Designer"s Guide to the Cortex-M Processor Family", Newnes, 2013. | | | | |

| 17AEPE14 | | SYSTEM ON CHIP DESIGN | [| L | Т | P | С |
|--|--|---|----------------|----------|----------|----------|--------|
| | | | | 3 | 0 | 0 | 3 |
| OBJEC | CTIVE | S: | | | | <u> </u> | |
| • | To u | derstand what SOC is and what the difference bet | ween SOC | and E | nbedde | ed sys | stem. |
| ٠ | To understand system design methodology in SOC. | | | | | | |
| • | To co | ver the basics of SOC design, hardware software | co design a | nd syn | thesis. | | |
| • | To st | ady different levels of SOC verification. | | | | | |
| • | To st | udy testing of SOC. | | | | | |
| UNIT I | | INTRODUCTION | | | | | 9 |
| embedded power So | l OS, m C Desig | | | | | | Low |
| UNIT I | I | SYSTEM LEVEL MODELLING | | | | | 9 |
| | | ew, Data types, modules, notion of time, dynami- orts and interfaces, Design with examples. | c process, | basic c | channels | s, stru | icture |
| UNIT I | II | HARDWARE AND SOFTWARE CO -DESIGN | | | | | 9 |
| • | nd pow | oning, high level optimisations, real-time scheduler management; Virtual platform models, co-simums. | - | | | | - |
| UNIT I | V | SYNTHESIS | | | | | 9 |
| mapping, communic | platforr cation; l | : Transaction Level Modelling (TLM) based desin a synthesis; software synthesis: code generation, multi Hardware synthesis: RTL architecture, Input models, ning and scheduling. | i task synth | esis, in | ternal a | nd ex | ternal |
| UNIT V | V | SOC VERIFICATION AND TESTING | | | | | 9 |
| system le | vel ver | ration, Verification: Verification technology options, fication, physical verification, hardware/software co C design for testability - System modeling, test power | o-verification | n; Test | require | ement | s and |
| | | ΤΟΤΑ | L: 45 I | PERI | ODS | | |
| OUTCO | OMES | : | | | | | |
| • | Analyse algorithms and architecture of hardware software in order to optimise the systemeters of the systeme | | | | | | /stem |
| • Analyse algorithms and architecture of hardware software in order to optimise the sy based on requirements and implementation constraints. | | | | | | | |
| • | | and specify systems at high level of abstraction. | | | | | |

| • | Understand hardware, software and interface synthesis. |
|------|--|
| • | Appreciate the co-design approach and virtual platform models. |
| • | Ability to do SOC verification and testing. |
| REFE | RENCES: |
| 1. | D. Black, J. Donovan, "SystemC: From the Ground Up", Springer, Second Edition, 2010. |
| 2. | D. Gajski, S. Abdi, A. Gerstlauer, G. Schirner, "Embedded System Design: Modeling, Synthesis, Verification", Springer, 2009 |
| 3. | H.Zhou, "The Internet of Things in the Cloud: A Middleware Perspective", CRC Press, 2012. |
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| 7. | M. L. Bushnell and V.D. Agrawal, "Essentials of Electronic Testing for Digital Memory and Mixed Signal VLSI Circuits", Springer, 2005 |
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| 10. | P.Rashinkar, P.Paterson and L.Singh, "System-on-a chip verification: Methodology and techniques", Kluwer Academic Publishers, 2002. |
| 11. | T. Noergaard, "Embedded Systems Architecture: A Comprehensive Guide for Engineers and Programmers", Newnes, Second Edition, 2012. |
| 12. | V.K. Madisetti, C.Arpikanondt, "A Platform-Centric Approach to System-on-Chip (SOC) Design", Springer, 2005. |
| 13. | Y.L Steve, Lin, "Essential Issues in SOC Design Designing Complex Systems-on-Chip", Springer, 2006. |

| 17AEPE15 | | ROBOTICS | L | Т | Р | С |
|--|--|---|--|---|------------------|--|
| | | | 3 | 0 | 0 | 3 |
| OBJEC | CTIVE | S: | | | 1 1 | |
| • | To ur | derstand robot locomotion and mobile robot kinematics. | | | | |
| ٠ | To ur | derstand perception in robotics. | | | | |
| • | To ur | derstand mobile robot localization. | | | | |
| • | To ur | derstand mobile robot mapping. | | | | |
| • | To ur | derstand robot planning and navigation. | | | | |
| UNIT I | [| LOCOMOTION AND KINEMATICS | | | | 9 |
| | | botics – key issues in robot locomotion – legged robots – wheele roduction to kinematics – kinematics models and constraints – robo | | | | aeria |
| UNIT I | Ι | ROBOT PERCEPTION | | | | 9 |
| | | | | | | |
| | | robots – vision for robotics – cameras – image formation – structur ical flow – color tracking – place recognition – range data | re fror | n sterec | o – stru | icture |
| | ion – opt | | re fror | n stered | o – stru | |
| from moti UNIT I Introducti map repre | ion – opt III ion to loo esentatio | ical flow – color tracking – place recognition – range data | ı – beli EKF 1 | ef repre | esenta | 9 tion – |
| from moti UNIT I Introducti map repre | ion – opt II Ion to locesentatio on – Grid | ical flow – color tracking – place recognition – range data MOBILE ROBOT LOCALIZATION alization – challenges in localization – localization and navigation n – probabilistic map-based localization – Markov localization – 1 | ı – beli EKF 1 | ef repre | esenta | 9 tion – UKF |
| from moti UNIT I Introducti map represented localization UNIT I Autonomo | ion – opt II ion to locesentatio on – Gric IV ous map Filter SL | ical flow – color tracking – place recognition – range data MOBILE ROBOT LOCALIZATION alization – challenges in localization – localization and navigation n – probabilistic map-based localization – Markov localization – 1 localization – Monte Carlo localization – localization in dynamic e | ı – beli EKF 1 enviror | lef repro ocaliza nments SLAM | esenta tion – | 9 tion – UKF 9 ended |
| from moti UNIT I Introducti map repre- localizatio UNIT I Autonomo Kalman F | ion – opt II ion to locesentatio on – Grid V ous map Filter SL gorithm. | A color tracking – place recognition – range data MOBILE ROBOT LOCALIZATION Palization – challenges in localization – localization and navigation A probabilistic map-based localization – Markov localization – 1 Iocalization – Monte Carlo localization – localization in dynamic e MOBILE ROBOT MAPPING building – occupancy grip mapping – MAP occupancy mapping | ı – beli EKF 1 enviror | lef repro ocaliza nments SLAM | esenta tion – | 9 tion – UKF 9 ended |
| from moti UNIT I Introducti map represented localization UNIT I Autonomotic Kalman F SLAM algo UNIT V Introduct | ion – opt III ion to locesentatio ion – Grid IV ous map Filter SL gorithm. | MOBILE ROBOT LOCALIZATION alization – challenges in localization – localization and navigation n – probabilistic map-based localization – Markov localization – T localization – Monte Carlo localization – localization in dynamic e MOBILE ROBOT MAPPING building – occupancy grip mapping – MAP occupancy mapping AM – graph-based SLAM – particle filter SLAM – sparse extended | i – beli EKF l enviroi ing – d infor | ef repro ocaliza nments SLAM mation | esenta tion – | 9 tion – UKF 9 endec – fast |
| from moti UNIT I Introducti map repre- localizatio UNIT I Autonomo Kalman F SLAM alg UNIT V Introduct | ion – opt III ion to locesentatio ion – Grid IV ous map Filter SL gorithm. | A color tracking – place recognition – range data MOBILE ROBOT LOCALIZATION alization – challenges in localization – localization and navigation a probabilistic map-based localization – Markov localization – illocalization – Monte Carlo localization – localization in dynamic e MOBILE ROBOT MAPPING building – occupancy grip mapping – MAP occupancy mapping AM – graph-based SLAM – particle filter SLAM – sparse extended PLANNING AND NAVIGATION lanning and navigation – planning and reacting – path planning | i – beli EKF 1 environ ing – d infor | ef repro ocaliza nments SLAM mation | esenta tion – | 9 tion - UKF 9 endec – fas |
| from moti UNIT I Introducti map repre- localizatio UNIT I Autonomo Kalman F SLAM alg UNIT V Introduct | ion – opt III ion to locesentatio on – Grid V ous map Filter SL gorithm. V tion to p es – nav | Antical flow – color tracking – place recognition – range data MOBILE ROBOT LOCALIZATION alization – challenges in localization – localization and navigation h – probabilistic map-based localization – Markov localization – flocalization – Monte Carlo localization – localization in dynamic e MOBILE ROBOT MAPPING building – occupancy grip mapping – MAP occupancy mapping M – graph-based SLAM – particle filter SLAM – sparse extended PLANNING AND NAVIGATION lanning and navigation – planning and reacting – path planning igation architectures – basic exploration algorithms. TOTAL : 45 P | i – beli EKF 1 environ ing – d infor | ef repro ocaliza nments SLAM mation | esenta tion – | 9 tion - UKF 9 endec – fas |
| from moti UNIT I Introducti map repre- localizatio UNIT I Autonome Kalman F SLAM alg UNIT V Introduct technique | ion – opt III Ion to locesentatio fon – Grid V ous map Filter SL gorithm. V tion to p es – nav | Antical flow – color tracking – place recognition – range data MOBILE ROBOT LOCALIZATION alization – challenges in localization – localization and navigation h – probabilistic map-based localization – Markov localization – flocalization – Monte Carlo localization – localization in dynamic e MOBILE ROBOT MAPPING building – occupancy grip mapping – MAP occupancy mapping M – graph-based SLAM – particle filter SLAM – sparse extended PLANNING AND NAVIGATION lanning and navigation – planning and reacting – path planning igation architectures – basic exploration algorithms. TOTAL : 45 P | i – beli EKF 1 environ ing – d infor | ef repro ocaliza nments SLAM mation | esenta tion – | 9 tion - UKF 9 endec – fas |
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| • | Implement robot localization techniques. |
|------|--|
| • | Implement robot mapping techniques. |
| • | Implement SLAM algorithms. |
| • | Understand the algorithms for planning and navigation in robotics. |
| REFE | RENCES: |
| 1. | G.Dudek, M.Jenkin, "Computational Principles of Mobile Robotics", Cambridge University Press, Second Edition, 2014. |
| 2. | H.Choset et al., "Principles of Robot Motion: Theory, Algorithms, and Implementations", A Bradford Book, 2005. |
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| P (| Т | L | RCUITS | EPE16 PHYSICAL DESIGN OF VLSI CIRCUI | EPE16 | 17AF |
|--|---|---|--|--|--|---|
| 0 3 | 0 | 3 | | | | |
| 1 | | | | CTIVES: | ECTIVES | OBJE(|
| layou | straction | cuit abs | out rules, circ | To introduce the physical design concepts such as layout rule methodologies and packaging. | | • |
| | | | ch. | To study placement of design using top down approach. | To stud | ٠ |
| | | | | To study different approaches of routing. | To stud | ٠ |
| | | | | To study performance issues in circuit layout. | To stud | ٠ |
| | | | | To study 1D compaction and 2D compaction. | To stud | ٠ |
| | | | OLOGY | I INTRODUCTION TO VLSI TECHNOLOG | I I | UNIT I |
| | program | , field p | nd sea of gates | Rules-Circuit abstraction Cell generation using programmable logic rrays and gate matrices-layout of standard cells gate arrays and sea o GA)-layout methodologies Packaging-Computational Complexity - A | arrays and ga | Berger ar |
| | | | | | | UNIT I |
| simulat simulat | pproach- nent by | ic Ratio hical ap placen | n-Lin Heuristi anning hierarc cted method- e network – | ing: Approximation of Hyper Graphs with Graphs, Kernighan-Lin H and i/o constrants. Floor planning: Rectangular dual floor planning l g- Floor plan sizing Placement: Cost function- force directed m g partitioning placement- module placement on a resistive network. | ning: Approx y and i/o con ng- Floor pl ng partitionin ent. | Partitionin capacity a annealing annealing placemen |
| simulat simulat ent line oaches oproac | pproach- nent by placen tial Apj ne Step | ic Ratio hical ap placen regular Sequent ting- O | n-Lin Heuristi anning hierarc cted method- e network – ROACH pal Routing: S | ing: Approximation of Hyper Graphs with Graphs, Kernighan-Lin H and i/o constrants. Floor planning: Rectangular dual floor planning l g- Floor plan sizing Placement: Cost function- force directed m g partitioning placement- module placement on a resistive network. | ning: Approx y and i/o con ng- Floor pl ng partitionin ent. TIII R nentals: Maz hial approach | Partitionin capacity a annealing annealing placemen UNIT I Fundamen hierarchia |
| simulat simulat ent line oaches oproac | pproach- nent by placen tial Apj ne Step | ic Ratio hical ap placen regular Sequent ting- O | n-Lin Heuristi anning hierarc cted method- e network – ROACH pal Routing: S | ing: Approximation of Hyper Graphs with Graphs, Kernighan-Lin H and i/o constrants. Floor planning: Rectangular dual floor planning l g- Floor plan sizing Placement: Cost function- force directed m g partitioning placement- module placement on a resistive netwo nt. III ROUTING USING TOP DOWN APPROAC entals: Maze Running- line searching- Steiner trees Global Rou al approaches - multi commodity flow based techniques - Randomise | ning: Approx y and i/o con ng- Floor pl ng partitionin ent. TIII R nentals: Maz hial approach Linear Prog. | Partitionin capacity a annealing placemen UNIT I Fundamen hierarchia Integer L |
| simulat simulat ent line oaches oproac | pproach- nent by placen tial Apj ne Step | ic Ratio hical ap placen regular Sequent ting- Or puting. I | n-Lin Heuristi anning hierarc cted method- e network – ROACH pal Routing: S ndomised Rou Switch box ro | ing: Approximation of Hyper Graphs with Graphs, Kernighan-Lin H and i/o constrants. Floor planning: Rectangular dual floor planning I g- Floor plan sizing Placement: Cost function- force directed ma g partitioning placement- module placement on a resistive network. III ROUTING USING TOP DOWN APPROAC entals: Maze Running- line searching- Steiner trees Global Rou al approaches - multi commodity flow based techniques - Randomise Linear Programming Detailed Routing: Channel Routing - Switch is sed FPGA- Row based FPGAs. | ning: Approx y and i/o con ng- Floor pl ng partitionin ent. CIIII R nentals: Maz hial approach Linear Prog- pased FPGA- | Partitionin capacity a annealing placemen UNIT I Fundamen hierarchia Integer L |
| simulat simulat ent line oaches pproac n FPG – Driv ng rivi | pproach- nent by placen tial App ne Step Routing | ic Ratio hical ap placen regular Sequent ting- Or outing. I UT C trees. g Appro | n-Lin Heuristi anning hierarc cted method- e network – ROACH bal Routing: S adomised Rou Switch box ro IT LAYO y- Delay in Re Programming k Trees. Mini | ing: Approximation of Hyper Graphs with Graphs, Kernighan-Lin H and i/o constrants. Floor planning: Rectangular dual floor planning I g- Floor plan sizing Placement: Cost function- force directed ma g partitioning placement- module placement on a resistive network. III ROUTING USING TOP DOWN APPROAC entals: Maze Running- line searching- Steiner trees Global Rou al approaches - multi commodity flow based techniques - Randomise Linear Programming Detailed Routing: Channel Routing - Switch is sed FPGA- Row based FPGAs. | ning: Approx y and i/o con ng- Floor pl ng partitionin ent. TIII R nentals: Maz hial approach Linear Prog based FPGA- TIV P. Models: Gate ent: Zero Sta g: Delay Mir | Partitionin capacity a annealing placemen UNIT 1 Fundamen hierarchia Integer L Array bas UNIT 1 Delay Mo Placemen Routing: |
| simulat simulat ent line oaches pproac n FPG – Driv ng rivi | pproach- nent by placen tial App ne Step Routing | ic Ratio hical ap placen regular Sequent ting- Op outing. I UT C trees g Appro mizatio | n-Lin Heuristi anning hierarc cted method- e network – ROACH bal Routing: S adomised Rou Switch box ro IT LAYO y- Delay in Re Programming k Trees. Mini zation. | ing: Approximation of Hyper Graphs with Graphs, Kernighan-Lin H and i/o constrants. Floor planning: Rectangular dual floor planning I g- Floor plan sizing Placement: Cost function- force directed m g partitioning placement- module placement on a resistive network. III ROUTING USING TOP DOWN APPROAC entals: Maze Running- line searching- Steiner trees Global Rou al approaches - multi commodity flow based techniques - Randomise Linear Programming Detailed Routing: Channel Routing - Switch sed FPGA- Row based FPGAs. IV PERFORMANCE ISSUES IN CIRCUIT LA fodels: Gate Delay Models- Models for interconnected Delay- Delay nt: Zero Stack Algorithm- Weight based placement- Linear Program Delay Minimization- Click Skew Problem- Buffered Clock Trees ation unconstrained via Minimization- Other issues in minimization. | ning: Approx y and i/o con ng- Floor pl ng partitionin ent. TIII R mentals: Maz hial approach Linear Prog- based FPGA- TIV P Models: Gate ent: Zero Sta g: Delay Mir zation uncons | Partitionin capacity a annealing placemen UNIT 1 Fundamen hierarchia Integer L Array bas UNIT 1 Delay Mo Placemen Routing: |
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| simulat simulat nt line oaches oproac n FPG – Driv ng rivi ained v | pproach- nent by placen tial App ne Step Routing . Timing bach Tin on: cons d Rout g Mult ger Arra | ic Ratio hical ap placen regular Sequent ting- On outing. I UT C trees Appro mizatio YION detailed Routing n Burg | n-Lin Heuristi anning hierarc cted method- e network – ROACH bal Routing: 5 ndomised Rou Switch box ro IT LAYOU y- Delay in Re Programming k Trees. Mini zation. GENERAT ingle Layer ell (OTC) F aining- Weir | ing: Approximation of Hyper Graphs with Graphs, Kernighan-Lin H and i/o constrants. Floor planning: Rectangular dual floor planning I g- Floor plan sizing Placement: Cost function- force directed me g partitioning placement- module placement on a resistive networt. III ROUTING USING TOP DOWN APPROAC entals: Maze Running- line searching- Steiner trees Global Rou al approaches - multi commodity flow based techniques - Randomise Linear Programming Detailed Routing: Channel Routing - Switch sed FPGA- Row based FPGAs. IV PERFORMANCE ISSUES IN CIRCUIT LA fodels: Gate Delay Models- Models for interconnected Delay- Delay nt: Zero Stack Algorithm- Weight based placement- Linear Program Delay Minimization- Click Skew Problem- Buffered Clock Trees ation unconstrained via Minimization- Other issues in minimization. V SINGLE LAYER ROUTING, CELL GENE AND COMPACTION subset problem(PSP)- Single Layer Global Routing- Single I and bend minimization technique – Over The Cell (Of G(MCM)- programmable Logic Arrays- Transistor chaining- | ning: Approx y and i/o con ng- Floor pl ng partitionin ent. TIII R nentals: Maz hial approach Linear Prog based FPGA- TIV P Models: Gate ent: Zero Sta g: Delay Min zation uncons TV SI A subset prot and bend es(MCM)- J | Partitionin capacity a annealing annealing placemen UNIT I Fundamen hierarchia Integer L Array bas UNIT I Delay Mo Placemen Routing: Minimiza UNIT V Planar su length a modules |

| OUTC | OMES: |
|-------|--|
| • | Exposure to the layout design methodologies. |
| • | Analyze placement and routing techniques. |
| • | Analyze performance issues in circuit layout. |
| • | Analyze techniques of single layer routing, cell generation and compaction. |
| • | Outline 1D compaction and 2D compaction. |
| REFER | RENCES: |
| 1. | P.M. Lorenzatti, "Physical Design and Automation of VLSI systems", The Benjamin Cummins Publishers, 1998. |
| 2. | Sarafzadeh, C.K. Wong, "An Introduction to VLSI Physical Design", McGraw Hill Int. Edition, 1995 |
| 3. | Michael S. Smith, "Application Specific Integrated Circuits", Addison-Wesley, 1997. |
| 4. | S.H. Gerez, "Algorithms for VLSI Design Automation", John Wiley & Sons, 2002. |

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|-------------|----------------------|--|---------|---------|--------|-----------|
| •] | WES. | | 3 | 0 | 0 | 3 |
| | IVE5: | | | 1 | | |
| •] | To deve | op a comprehensive understanding of multimedia networ | ·ks. | | | |
| | To study | the types of VPN and tunnelling protocols for security. | | | | |
| •] | To learn | about network security in many layers and network mana | agemen | t. | | |
| •] | To study | advanced network concepts. | | | | |
| •] | To discu | ss traffic modelling. | | | | |
| UNIT I | IN | TRODUCTION | | | | 9 |
| | | CP/IP; Multiplexing, Modes of Communication, Switch DN – BISDN, ATM. | ing, Ro | outing. | SON | ЕТ – |
| UNIT II | Μ | ULTIMEDIA NETWORKING APPLICATIO | ONS | | | 9 |
| UNIT III | erentiate | ond best effort – scheduling and policing mechanism d services. | – integ | grated | | - ces |
| | unneling | ss VPN, site-to-site VPN, Tunneling to PPP, Security in and use of FEC, Traffic Engineering, and MPLS based | | | - | |
| UNIT IV | TI | RAFFIC MODELLING | | | | 9 |
| | | Need for modeling, Poisson modeling and its failure, ce evaluation. | Non- | poisso | n mo | odels, |
| UNIT V | N | ETWORK SECURITY AND MANAGEMENT | Г | | | 9 |
| control and | fire wa mageme | graphy – Authentication – integrity – key distribution an Ils – attacks and counter measures – security in many la nt – The internet standard management framework – SM - ASN.1 | ayers. | Infrast | ructur | re for |
| | | TOTAL : 45 | PERI | ODS | | |
| OUTCON | MES: | | | | | |
| | Analyze pplicatio | scheduling and policing mechanism and protocols forms. | or real | time | intera | ctive |
| • D | Discuss a | dvanced networks concepts. | | | | |

| • | Outline traffic modelling. |
|------|---|
| • | Evaluate network security and management. |
| • | Evaluate network performance. |
| REFE | RENCES: |
| 1. | A.Kumar, D. M Anjunath, J.Kuri, "Communication Networking", Morgan Kaufmann Publishers, 1st edition, 2004. |
| 2. | F.Halsall and L.G Kulkarni, "Computer Networking and the Internet", fifth edition, Pearson education 2006. |
| 3. | H.Gurle & Petit, "IP Telephony, packet Pored Multimedia communication Systems", Pearson education 2003. |
| 4. | J.F. Kurose & K.W. Ross, "Computer Networking- A top down approach featuring the internet", Pearson, 2nd edition, 2003. |
| 5. | L.l.Peterson & B.S.David, "Computer Networks: A System Approach", Morgan Kaufmann Publishers, Fifth Edition, 2011. |
| 6. | LEOM-GarCIA, WIDJAJA, "Communication networks", TMH, Second Edition, 2004. |
| 7. | N.F.Mir, "Computer and Communication Networks", Second Edition, Prentice Hall of India, 2014. |
| 8. | WJ. Varatya, "High performance communication network", Morgan Kauffman – Harcourt Asia Pvt. Ltd, 2nd Edition, 2000. |

SEMESTER- III

ELECTIVE V

| 17AEPE | 18 | PATTERN RECOGNITION | L | Т | Р | C |
|---------------------------|--------|---|------------------|-------|-------|----------|
| | | | 3 | 0 | 0 | 3 |
| OBJECT | TIVE | S: | | 1 | 1 | |
| • | To lea | arn about supervised and unsupervised pattern classifiers | | | | |
| • | To lea | arn about different clustering methods. | | | | |
| • | To fa | miliarize about different feature extraction techniques | | | | |
| • | To ex | plore the role of Hidden Marko model and SVM in pattern reco | ogni | ion | | |
| • | To un | derstand the application of Fuzzy logic and genetic algorithms | for _l | patte | rn cl | assifier |
| UNIT I | | PATTERN CLASSIFIER | | | | 9 |
| estimation | – Ma | attern recognition – Discriminant functions – Supervised Eximum Likelihood Estimation – Bayesian parameter Estimat - Pattern classification by distance functions – Minimum distan | ion | - P1 | oble | ms with |
| UNIT II | | CLUSTERING | | | | 9 |
| - | | nsupervised learning and classification–Clustering concept – Content of the tering – Graph theoretic approach to pattern Clustering – Valid | | | - | |
| UNIT III | [| FEATURE EXTRACTION AND STRUCTURAL PATTERN RECOGNITION | , | | | 9 |
| ÷ . | ivers | ds, Addressing Modes, Stack and Buffer Overflow, FIFO a and OS Security; Secure Design Principles, Trusted Operati s | | | | |
| UNIT IV | r | HIDDEN MARKOV MODELS AND SUPPORT VECTOR MACHINE | | | | 9 |
| State Mach Feature Sel | | - Hidden Markov Models – Training – Classification – Suppon. | ort v | vecto | or Ma | achine – |
| UNIT V | | RECENT ADVANCES | | | | 9 |
| | | uzzy Pattern Classifiers – Pattern Classification using Geneti zy Pattern Classifiers and Perception. | c Al | gori | thms | s – Case |

| | TOTAL : 45 PERIODS |
|------|--|
| OUTC | OMES: |
| • | Differentiate between supervised and unsupervised classifiers |
| • | Classify the data and identify the patterns. |
| • | Apply the concepts of clustering |
| • | Extract feature set and select the features from given data set. |
| • | Apply fuzzy logic and genetic algorithms for classification problems |
| REFE | RENCES: |
| 1. | Andrew Webb, "Stastical Pattern Recognition", Arnold publishers, London, 1999 |
| 2. | C.M.Bishop, "Pattern Recognition and Machine Learning", Springer, 2006. |
| 3. | M. Narasimha Murthy and V. Susheela Devi, "Pattern Recognition", Springer 2011. |
| 4. | Menahem Friedman, Abraham Kandel, "Introduction to Pattern Recognition Statistical, Structural, Neural and Fuzzy Logic Approaches", World Scientific publishing Co. Ltd, 2000. |
| 5. | Robert J.Schalkoff, "Pattern Recognition Statistical, Structural and Neural Approaches", John Wiley & Sons Inc., New York, 1992. |
| 6. | R.O.Duda, P.E.Hart and D.G.Stork, "Pattern Classification", John Wiley, 2001 |
| 7. | S. Theodoridis and K. Koutroumbas, "Pattern Recognition", 4th Ed., Academic Press. 2009. |

| 17AEP | E19 | SECURE COMPUTING SYSTEMS L | | Т | Р | C |
|--|--|--|-------------|---|--|--|
| | | 3 | (| 0 | 0 | 3 |
| OBJE | CTIVE | ZS: | | | | |
| ٠ | To le | arn different computer security mechanism and management techni | iqı | ues | | |
| • | To ga | ain knowledge about computer hardware security. | | | | |
| ٠ | To ap | pply programming knowledge in hardware. | | | | |
| ٠ | To le | arn advanced computer architecture. | | | | |
| • | To le | arn the equation and theory those are used in network security. | | | | |
| UNIT I | [| COMPUTER SECURITY AND MANAGEMENT | | | | 9 |
| Security | Manag | mputer Security, Threats, Malware, Vulnerabilities, Authentication gement Models, Security Management Practices, Protection Me ty, Ethical Hacking. | | | | |
| | UNIT II HARDWARF SECURITY | | | 9 | | |
| Interface, | Hardwa CPU; | HARDWARE SECURITY are Security, Computer Memory and storage, Bus and Interconnection, Side channel Analysis: Power Analysis Attack, Timing Atta of Side Channel Attack Secure Hardware Intellectual Properties Phy | ıck | z,] | Fault | attack. |
| Need for Interface, Counterm | Hardwa CPU; neasures s(PUFs), | re Security, Computer Memory and storage, Bus and Interconnection, | ıck | z,] | Fault | Network attack. aclonable |
| Need for Interface, Counterm Functions | Hardwa CPU; neasures s(PUFs), | are Security, Computer Memory and storage, Bus and Interconnection, Side channel Analysis: Power Analysis Attack, Timing Atta of Side Channel Attack, Secure Hardware Intellectual Properties, Phy Secure PUF. | ıck | z,] | Fault | Network attack. aclonable |
| Need for Interface, Counterm Functions UNIT I Opcode, | Hardwa CPU; neasures s(PUFs), III Operar Drivers | are Security, Computer Memory and storage, Bus and Interconnection, Side channel Analysis: Power Analysis Attack, Timing Atta of Side Channel Attack, Secure Hardware Intellectual Properties, Phy Secure PUF. ASSEMBLY AND OPERATING SYSTEMS SECURITY ands, Addressing Modes, Stack and Buffer Overflow, FIFO and and OS Security; Secure Design Principles, Trusted Operating | ick /sid | r, 1 call | Fault y Ur | Network attack. aclonable 9 Problem, |
| Need for Interface, Counterm Functions UNIT I Opcode, Kernel, | Hardwa CPU; neasures s(PUFs), III Operar Drivers Functior | are Security, Computer Memory and storage, Bus and Interconnection, Side channel Analysis: Power Analysis Attack, Timing Atta of Side Channel Attack, Secure Hardware Intellectual Properties, Phy Secure PUF. ASSEMBLY AND OPERATING SYSTEMS SECURITY ands, Addressing Modes, Stack and Buffer Overflow, FIFO and and OS Security; Secure Design Principles, Trusted Operating | ick /sid | r, 1 call | Fault y Ur | Network attack. Inclonable 9 Problem, |
| Need for Interface, Counterm Functions UNIT I Opcode, Kernel, System F UNIT I Security | Hardwa CPU; neasures s(PUFs), III Operar Drivers Functior IV aspects | are Security, Computer Memory and storage, Bus and Interconnection, Side channel Analysis: Power Analysis Attack, Timing Atta of Side Channel Attack, Secure Hardware Intellectual Properties, Phy Secure PUF. ASSEMBLY AND OPERATING SYSTEMS SECURITY ands, Addressing Modes, Stack and Buffer Overflow, FIFO and and OS Security; Secure Design Principles, Trusted Operating as | M Sy | s,] call I/M yste | Fault y Ur //1 F ems, | Network attack. aclonable 9 Problem, Trusted 9 |
| Need for Interface, Counterm Functions UNIT I Opcode, Kernel, System F UNIT I Security | Hardwa CPU; neasures s(PUFs), III Operar Drivers Functior IV aspects mputing | Are Security, Computer Memory and storage, Bus and Interconnection, Side channel Analysis: Power Analysis Attack, Timing Atta of Side Channel Attack, Secure Hardware Intellectual Properties, Phy Secure PUF. ASSEMBLY AND OPERATING SYSTEMS SECURITY ands, Addressing Modes, Stack and Buffer Overflow, FIFO and and OS Security; Secure Design Principles, Trusted Operating assecurity and Computer Architecture ADVANCED COMPUTER ARCHITECTURE : Multiprocessors, parallel processing, Ubiquitous computing, Grid | M Sy | s,] call I/M yste | Fault y Ur //1 F ems, | Network attack. Inclonable 9 Problem, Trusted 9 uted and |
| Need for Interface, Countern Functions UNIT 1 Opcode, Kernel, 2 System F UNIT 1 Security cloud co UNIT 1 Atomic 3 Equation | Hardwa CPU; heasures s(PUFs), III Operar Drivers Function IV aspects mputing V Structur h and W | Assembly And Operating Systems Assembly And Operating Systems Secure PUF. Assembly And Operating Systems Secure PUF. Assembly And Operating Systems Security and os Security; Secure Design Principles, Trusted Operating Advanced Computer Architecture : Multiprocessors, parallel processing, Ubiquitous computing, Grid g, Internet computing, Virtualization | M Sy d, | a, 1 call I/M yste Dis cs: an | Fault y Ur [/1 F ems, stribu | Network attack. helonable 9 Problem, Trusted 9 uted and 9 uted and 9 |

| OUTCOM | ES: |
|---------|---|
| • | Aware of Security aspects |
| • | Able to appreciate security in hardware, OS and it future need |
| • | Learn security issues in various types of computing networks |
| • | Learn advanced computer architecture. |
| • | Outline the equation and theory which are used in web security. |
| REFEREN | ICES: |
| 1. | Charles B. Pfleeger, Shari Lawrence Pfleeger, "Security in Computing", Fourth Edition, Pearson Education, 2007 |
| 2. | Debdeep Mukhopadhyay, Rajat Subhra Chakraborty, "Hardware Security - Design Threats and Safeguards", CRC Press, 2015 |
| 3. | Michael Whitman, Herbert J. Mattord, "Management of Information Security", Third Edition, Course Technology, 2010 |
| 4. | Shuangbao Wang, Robert S.Ledley, Computer Architecture and Security, Wiley, 2013 |
| 5. | William Stallings, "Network Security Essentials, Applications and Standards", Dorling Kindersley I P Ltd, Delhi, 2008. |
| 6. | Charles B. Pfleeger, Shari Lawrence Pfleeger, "Security in Computing", Fourth Edition, Pearson Education, 2007 |
| 7. | Debdeep Mukhopadhyay, Rajat Subhra Chakraborty, "Hardware Security - Design Threats and Safeguards", CRC Press, 2015 |

| | E20 SI | 17AEP |
|--|-------------------|---------------------------|
| 3 0 0 3 | | |
| | CTIVES: | OBJEC |
| its. | To identify s | • |
| ion characteristics | To introduce | • |
| | To learn non | • |
| oscillators. | To gain know | • |
| | To analyze th | ٠ |
| SION LINES | [SIGN | UNIT I |
| | line Reflection | and stripl into a trai |
| JINES AND | I MUL' CROS | UNIT I |
| ength parameters ,Near and far-en Differential signalling, termination | | cross-talk |
| | III NON- | UNIT I |
| sitions , Parasitic inductance an parasitic, Common-mode curren | U U | capacitan |
| M DESIGN | IV POW | UNIT I |
| ecoupling , Logic families, powe speed Package types and parasitions of link-path components , Ey | otion, and syste | consump ,SPICE, |
| ; analysis | , jitter, inter s | ulagrams |
| s analysis | | |

| | TOTAL : 45 PERIODS |
|------|---|
| OUTC | OMES: |
| ٠ | Ability to identify sources affecting the speed of digital circuits |
| • | Able to improve the signal transmission characteristics. |
| • | Understand clock distribution and clock oscillators. |
| • | Learn Multi-conductor transmission line and crosstalk. |
| • | Learn Power consideration and system design for high speed design. |
| REFE | RENCES: |
| 1. | Douglas Brooks, Signal Integrity Issues and Printed Circuit Board Design, Prentice Hall PTR, 2003 |
| 2. | Eric Bogatin, Signal Integrity – Simplified, Prentice Hall PTR, 2003. |
| 3. | H. W. Johnson and M. Graham, High-Speed Digital Design: A Handbook of Black Magic, Prentice Hall, 1993. |
| 4. | S. Hall, G. Hall, and J. McCall, High-Speed Digital System Design: A Handbook of Interconnect Theory and Design Practices, Wiley-Interscience, 2000. |

| 17AEPE | 21 WIRELESS ADHOC AND SENSOR NETWORKS | L | T | Р | С |
|--------------|---|---|---|---|----------|
| | | 3 | 0 | 0 | 3 |
| OBJEC | TIVES: | | | | <u>.</u> |
| • | To study the ADHOC networks and its protocols | | | | |

| UNIT I | MAC & TCD IN AD HOC NETWODKS | 0 |
|--------|--|---|
| • | To explore the sensor networks and operating systems | |
| • | To study the sensor networks and MAC protocols | |
| • | To study the Challenges in QOS and power management schemes | |
| • | To implement the designing of multicast routing and security | |
| | To study the ribitoe networks and its protocols | |

MAC & TCP IN AD HOC NETWORKS

9

Fundamentals of WLANs - IEEE 802.11 Architecture - Self configuration and Auto configuration-Issues in Ad-Hoc Wireless Networks - MAC Protocols for Ad-Hoc Wireless Networks - Contention Based Protocols - TCP over Ad-Hoc networks-TCP protocol overview - TCP and MANETs -Solutions for TCP over Ad-Hoc Networks.

UNIT II

ROUTING IN AD HOC NETWORKS

9

Routing in Ad-Hoc Networks- Introduction-Topology based versus Position based Approaches-Proactive, Reactive, Hybrid Routing Approach-Principles and issues – Location services - DREAM - Quorums based location service - Grid - Forwarding strategies - Greedy packet forwarding -Restricted directional flooding- Hierarchical Routing- Issues and Challenges in providing QoS.

UNIT III

MAC, ROUTING & OOS IN WIRELESS SENSOR **NETWORKS**

9

9

Introduction - Architecture - Single node architecture - Sensor network design considerations -Energy Efficient Design principles for WSNs - Protocols for WSN - Physical Layer : Transceiver Design considerations - MAC Layer Protocols - IEEE 802.15.4 Zigbee - Link Layer and Error Control issues - Routing Protocols – Mobile Nodes and Mobile Robots - Data Centric & Contention Based Networking - Transport Protocols & QOS - Congestion Control issues - Application Layer support.

UNIT IV SENSOR MANAGEMENT

Sensor Management - Topology Control Protocols and Sensing Mode Selection Protocols - Time synchronization - Localization and positioning - Operating systems and Sensor Network programming - Sensor Network Simulators.

| UNIT V | SECURITY IN AD HOC AND SENSOR NETWORKS |
|----------------------------------|--|
| Anti-tamper tee Adhoc routing | -Hoc and Sensor networks – Key Distribution and Management – Software base chniques – water marking techniques – Defence against routing attacks - Secur protocols – Broadcast authentication WSN protocols – TESLA – Biba – Senso ity Protocols – SPINS. |
| | TOTAL : 45 PERIODS |
| OUTCOME | S: |
| • Ide | ntify different issues in wireless ad hoc and sensor networks. |
| • An | alyze protocols developed for ad hoc and sensor networks. |
| • Ou | tline different routing techniques and challenges in providing Qos. |
| • Ide | entify and address the security threats in ad hoc and sensor networks. |
| • Est | ablish a Sensor network environment for different type of applications. |
| REFERENC | CES: |
| | arlos De Morais Cordeiro, Dharma Prakash Agrawal "Ad Hoc and Sensc etworks: Theory and Applications (2nd Edition), World Scientific Publishing, 2011 |
| | Siva Ram Murthy and B.S.Manoj, "Ad Hoc Wireless Networks – Architectures an otocols", Pearson Education, 2004. |
| 3. С. | K.Toh, "Ad Hoc Mobile Wireless Networks", Pearson Education, 2002. |
| | dal Çayırcı , Chunming Rong, "Security in Wireless Ad Hoc and Sensor Networks", Joh iley and Sons, 2009. |
| | olger Karl, Andreas willig, Protocols and Architectures for Wireless Sensor Networks, Joh iley & Sons, Inc .2005. |
| | bir Kumar Sarkar, T G Basavaraju, C Puttamadappa, "Ad Hoc Mobile Wireless Networks verbach Publications, 2008. |
| | altenegus Dargie, Christian Poellabauer, "Fundamentals of Wireless Sensor Network eory and Practice", John Wiley and Sons, 2010. |